

SSD0300

Advance Information

**104 x 48 Dot Matrix
OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice

TABLE OF CONTENTS

1 GENERAL INFORMATION.....	5
2 FEATURES.....	5
3 ORDERING INFORMATION.....	5
4 BLOCK DIAGRAM.....	6
5 SSD0300 GOLD-BUMP DIE PAD ASSIGNMENT	7
6 PIN DESCRIPTION.....	11
7 MPU INTERFACES DESCRIPTIONS.....	14
MPU I ² C INTERFACE.....	14
I ² C-BUS WRITE DATA AND READ REGISTER STATUS	15
MPU PARALLEL 6800-SERIES INTERFACE.....	19
MPU PARALLEL 8080-SERIES INTERFACE.....	19
MPU SERIAL INTERFACE.....	20
8 FUNCTIONAL BLOCK DESCRIPTIONS	21
OSCILLATOR CIRCUIT AND DISPLAY TIME GENERATOR.....	21
RESET CIRCUIT	21
COMMAND DECODER AND COMMAND INTERFACE.....	21
GRAPHIC DISPLAY DATA RAM (GDDRAM).....	22
CURRENT CONTROL AND VOLTAGE CONTROL	23
SEGMENT DRIVERS/COMMON DRIVERS	23
AREA COLOUR DECODER	23
DC-DC VOLTAGE CONVERTER	24
9 COMMAND TABLE.....	26
DATA READ / WRITE	29
10 COMMAND DESCRIPTIONS	30
11 MAXIMUM RATINGS.....	36
12 DC CHARACTERISTICS.....	37
13 AC CHARACTERISTICS.....	38
14 TIMING CHARACTERISTICS	39
15 APPLICATION EXAMPLE	43
16 SSD0300TR1 TAB PACKAGE	44
SSD0300TR1 PIN ASSIGNMENT.....	44
SSD0300TR1 TAB DETAILS DIMENSIONS.....	46
17 SSD0300T3R1 TAB PACKAGE	48
SSD0300T3R1 PIN ASSIGNMENT.....	48
SSD0300T3R1 TAB DETAILS DIMENSIONS.....	50
TAB MARKING DESCRIPTION	51

TABLE OF FIGURES

FIGURE 1 - BLOCK DIAGRAM.....	6
FIGURE 2 - SSD0300Z PIN ASSIGNMENT.....	7
FIGURE 3 - SSD0300Z ALIGNMENT MARK DIMENSIONS	10
FIGURE 4 - I ² C-BUS DATA FORMAT	15
FIGURE 5 - DEFINITION OF THE START AND STOP CONDITION	16
FIGURE 6 - DEFINITION OF THE ACKNOWLEDGEMENT CONDITION	17
FIGURE 7 - DEFINITION OF THE DATA TRANSFER CONDITION	17
FIGURE 8 - DISPLAY DATA READ BACK PROCEDURE - INSERTION OF DUMMY READ.....	19
FIGURE 9 - DISPLAY DATA WRITE PROCEDURE IN SPI MODE.....	20
FIGURE 10 - OSCILLATOR CIRCUIT	21
FIGURE 11 - GDDRAM PAGES STRUCTURE OF SSD0300.....	22
FIGURE 12 - EXAMPLE OF GDDRAM ACCESS LOCATION SETTING (NO ROW RE-MAPPING & COLUMN-REMAPPING) ...	22
FIGURE 13 - EXAMPLE OF AREA COLOR ASSIGNMENT ON A 104x48 OLED PANEL.....	23
FIGURE 14 - DC-DC VOLTAGE CONVERTER CIRCUIT	24
FIGURE 15 - HORIZONTAL SCROLL DIRECTION.....	30
FIGURE 16 - SEGMENT CURRENT VS CONTRAST SETTING	31
FIGURE 17 - I ² C INTERFACE CHARACTERISTICS	39
FIGURE 18 - 6800-SERIES MPU PARALLEL INTERFACE CHARACTERISTICS	40
FIGURE 19 - 8080-SERIES MPU PARALLEL INTERFACE CHARACTERISTICS	41
FIGURE 20 - SERIAL INTERFACE CHARACTERISTICS	42
FIGURE 21 - APPLICATION EXAMPLE FOR SSD0300	43
FIGURE 22 - SSD0300TR1 PIN ASSIGNMENT	44
FIGURE 23- SSD0300TR1 DETAIL DIMENSIONS	46
FIGURE 24 - SSD0300T3R1 PIN ASSIGNMENT (COPPER VIEW)	48
FIGURE 25- SSD0300T3R1 DETAIL DIMENSIONS	50

LIST OF TABLES

TABLE 1 - ORDERING INFORMATION	5
TABLE 2 - SSD0300Z DIE PAD COORDINATES	8
TABLE 3 - PASSIVE COMPONENT SELECTION:	25
TABLE 4 - COMMAND TABLE	26
TABLE 5 - READ COMMAND TABLE.....	28
TABLE 6 - ADDRESS INCREMENT TABLE (AUTOMATIC)	29
TABLE 7 - MAXIMUM RATINGS (VOLTAGE REFERENCE TO V _{SS})	36
TABLE 8 - DC CHARACTERISTICS.....	37
TABLE 9 - AC CHARACTERISTICS.....	38
TABLE 10 - I ² C INTERFACE TIMING CHARACTERISTICS (V _{DD} -V _{SS} =2.4 TO 3.5V, T _A =-40 TO 85° C)	39
TABLE 11 - 6800-SERIES MPU PARALLEL INTERFACE TIMING CHARACTERISTICS	40
TABLE 12 - 8080-SERIES MPU PARALLEL INTERFACE TIMING CHARACTERISTICS	41
TABLE 13 - SERIAL INTERFACE TIMING CHARACTERISTICS	42
TABLE 14 - SSD0300TR1 PIN ASSIGNMENT	45
TABLE 15 - SSD0300T3R1 PIN ASSIGNMENT	49

1 GENERAL INFORMATION

SSD0300 is a single-chip CMOS OLED/PLED driver with controller for organic/polymer light emitting diode dot-matrix graphic display system. SSD0300 consists of 104 segments, 48 commons that can support a maximum display resolution of 104x48. Besides, there are 4 colours selection to support monochrome or area colour OLED/PLED. This IC is designed for Common Cathode type OLED panel.

SSD0300 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. SSD0300 is suitable for many compact portable applications, such as mobile phone sub-display, calculator and MP3 player, etc.

2 FEATURES

- Support maximum 104 x 48 dot matrix panel
- Area colour support with 4 colours selection and 64 steps per colour
- Logic voltage supply: $V_{DD}=2.4V - 3.5V$
- High voltage supply: $V_{CC}=7.0V - 16.0V$
- Segment output current: 320 μ A
- Maximum common sink current: 45mA
- Embedded 104x48 bit SRAM display buffer
- 256-step contrast control on monochrome passive OLED panel
- On-Chip Oscillator
- Programmable Frame Frequency and Multiplexing Ratio
- I²C interface, 8-bit 6800-series Parallel Interface, 8-bit 8080-series Parallel Interface, Serial Peripheral Interface
- Row re-mapping and Column re-mapping
- Vertical scrolling
- Automatic horizontal scrolling function
- Low power consumption
- Wide range of operating temperatures: -40 to 85 °C

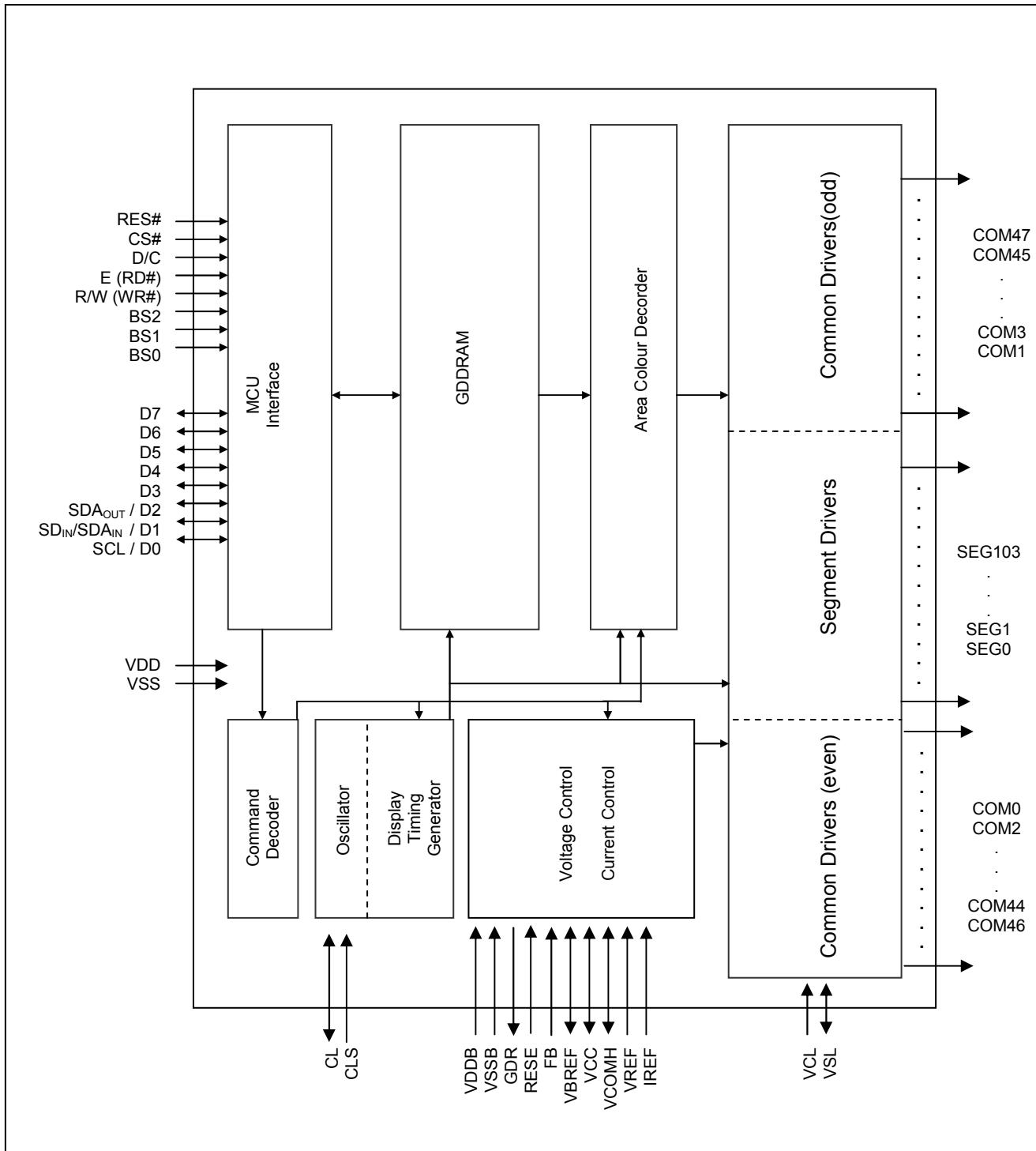
3 ORDERING INFORMATION

Table 1 - Ordering Information

Ordering Part Number	SEG	COM	Package Form	Reference	Remark
SSD0300Z	104	48	Gold Bump Die	Page 6	Die size: 7.29mm x 1.56mm Pad pitch: COM 51.8 μ m SEG 52.2 μ m I ² C interface
SSD0300TR1	96	48	TAB	Page 44	<ul style="list-style-type: none">• 35mm film• 4 sprocket hole• I²C interface• Folding TAB• Output lead pitch 0.0997mm
SSD0300T3R1	96	48	TAB	Page 48	<ul style="list-style-type: none">• 35mm film• 4 sprocket hole• I²C interface• Folding TAB• Output lead pitch 0.12974mm

4 BLOCK DIAGRAM

Figure 1 - Block Diagram



5 SSD0300 GOLD-BUMP DIE PAD ASSIGNMENT

Figure 2 - SSD0300Z Pin Assignment

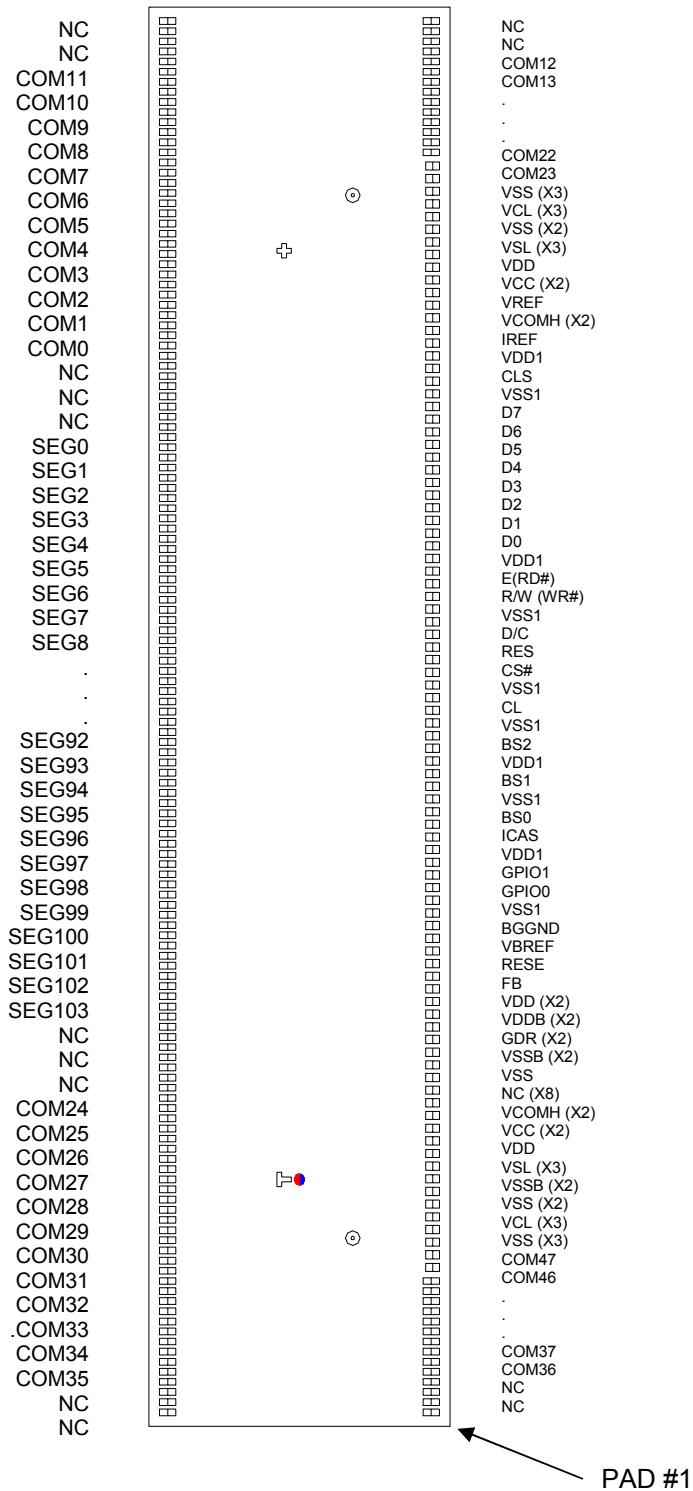
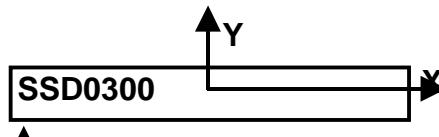


Table 2 - SSD0300Z Die Pad Coordinates

Pad no.	Signal	X-pos	Y-pos	Pad no.	Signal	X-pos	Y-pos	Pad no.	Signal	X-pos	Y-pos
1	NC	-3571.3	-679.6	61	BS1	162.5	-686.6	121	COM9	3363.3	679.6
2	NC	-3519.1	-679.6	62	VDD1	227.5	-686.6	122	COM8	3311.5	679.6
3	COM36	-3466.9	-679.6	63	BS2	292.5	-686.6	123	COM7	3259.7	679.6
4	COM37	-3415.1	-679.6	64	VSS1	357.5	-686.6	124	COM6	3207.9	679.6
5	COM38	-3363.3	-679.6	65	CL	422.5	-686.6	125	COM5	3156.1	679.6
6	COM39	-3311.5	-679.6	66	VSS1	487.5	-686.6	126	COM4	3104.3	679.6
7	COM40	-3259.7	-679.6	67	CSB	552.5	-686.6	127	COM3	3052.5	679.6
8	COM41	-3207.9	-679.6	68	RES	617.5	-686.6	128	COM2	3000.7	679.6
9	COM42	-3156.1	-679.6	69	D/C	682.5	-686.6	129	COM1	2948.9	679.6
10	COM43	-3104.3	-679.6	70	VSS1	747.5	-686.6	130	COM0	2897.1	679.6
11	COM44	-3052.5	-679.6	71	R/W (WR#)	812.5	-686.6	131	NC	2844.9	679.6
12	COM45	-3000.7	-679.6	72	E(RD#)	877.5	-686.6	132	NC	2792.7	679.6
13	COM46	-2948.9	-679.6	73	VDD1	942.5	-686.6	133	NC	2740.5	679.6
14	COM47	-2897.1	-679.6	74	D0	1007.5	-686.6	134	SEG0	2688.3	679.6
15	VSS	-2827.5	-686.6	75	D1	1072.5	-686.6	135	SEG1	2636.1	679.6
16	VSS	-2762.5	-686.6	76	D2	1137.5	-686.6	136	SEG2	2583.9	679.6
17	VSS	-2697.5	-686.6	77	D3	1202.5	-686.6	137	SEG3	2531.7	679.6
18	VCL	-2632.5	-686.6	78	D4	1267.5	-686.6	138	SEG4	2479.5	679.6
19	VCL	-2567.5	-686.6	79	D5	1332.5	-686.6	139	SEG5	2427.3	679.6
20	VCL	-2502.5	-686.6	80	D6	1397.5	-686.6	140	SEG6	2375.1	679.6
21	VSS	-2437.5	-686.6	81	D7	1462.5	-686.6	141	SEG7	2322.9	679.6
22	VSS	-2372.5	-686.6	82	VSS1	1527.5	-686.6	142	SEG8	2270.7	679.6
23	VSSBUF	-2307.5	-686.6	83	CLS	1592.5	-686.6	143	SEG9	2218.5	679.6
24	VSSBUF	-2242.5	-686.6	84	VDD1	1657.5	-686.6	144	SEG10	2166.3	679.6
25	VSL	-2177.5	-686.6	85	IREF	1722.5	-686.6	145	SEG11	2114.1	679.6
26	VSL	-2112.5	-686.6	86	VCOMH	1787.5	-686.6	146	SEG12	2061.9	679.6
27	VSL	-2047.5	-686.6	87	VCOMH	1852.5	-686.6	147	SEG13	2009.7	679.6
28	VDD	-1982.5	-686.6	88	VREF	1917.5	-686.6	148	SEG14	1957.5	679.6
29	VCC	-1917.5	-686.6	89	VCC	1982.5	-686.6	149	SEG15	1905.3	679.6
30	VCC	-1852.5	-686.6	90	VCC	2047.5	-686.6	150	SEG16	1853.1	679.6
31	VCOMH	-1787.5	-686.6	91	VDD	2112.5	-686.6	151	SEG17	1800.9	679.6
32	VCOMH	-1722.5	-686.6	92	VSL	2177.5	-686.6	152	SEG18	1748.7	679.6
33	NC	-1657.5	-686.6	93	VSL	2242.5	-686.6	153	SEG19	1696.5	679.6
34	NC	-1592.5	-686.6	94	VSL	2307.5	-686.6	154	SEG20	1644.3	679.6
35	NC	-1527.5	-686.6	95	VSS	2372.5	-686.6	155	SEG21	1592.1	679.6
36	NC	-1462.5	-686.6	96	VSS	2437.5	-686.6	156	SEG22	1539.9	679.6
37	NC	-1397.5	-686.6	97	VCL	2502.5	-686.6	157	SEG23	1487.7	679.6
38	NC	-1332.5	-686.6	98	VCL	2567.5	-686.6	158	SEG24	1435.5	679.6
39	NC	-1267.5	-686.6	99	VCL	2632.5	-686.6	159	SEG25	1383.3	679.6
40	NC	-1202.5	-686.6	100	VSS	2697.5	-686.6	160	SEG26	1331.1	679.6
41	VSS	-1137.5	-686.6	101	VSS	2762.5	-686.6	161	SEG27	1278.9	679.6
42	VSSBUF	-1072.5	-686.6	102	VSS	2827.5	-686.6	162	SEG28	1226.7	679.6
43	VSSBUF	-1007.5	-686.6	103	COM23	2897.1	-679.6	163	SEG29	1174.5	679.6
44	GDR	-942.5	-686.6	104	COM22	2948.9	-679.6	164	SEG30	1122.3	679.6
45	GDR	-877.5	-686.6	105	COM21	3000.7	-679.6	165	SEG31	1070.1	679.6
46	VDDBUF	-812.5	-686.6	106	COM20	3052.5	-679.6	166	SEG32	1017.9	679.6
47	VDDBUF	-747.5	-686.6	107	COM19	3104.3	-679.6	167	SEG33	965.7	679.6
48	VDD	-682.5	-686.6	108	COM18	3156.1	-679.6	168	SEG34	913.5	679.6
49	VDD	-617.5	-686.6	109	COM17	3207.9	-679.6	169	SEG35	861.3	679.6
50	FB	-552.5	-686.6	110	COM16	3259.7	-679.6	170	SEG36	809.1	679.6
51	RESE	-487.5	-686.6	111	COM15	3311.5	-679.6	171	SEG37	756.9	679.6
52	VBREF	-422.5	-686.6	112	COM14	3363.3	-679.6	172	SEG38	704.7	679.6
53	BGND	-357.5	-686.6	113	COM13	3415.1	-679.6	173	SEG39	652.5	679.6
54	VSS1	-292.5	-686.6	114	COM12	3466.9	-679.6	174	SEG40	600.3	679.6
55	GPIO0	-227.5	-686.6	115	NC	3519.1	-679.6	175	SEG41	548.1	679.6
56	GPIO1	-162.5	-686.6	116	NC	3571.3	-679.6	176	SEG42	495.9	679.6
57	VDD1	-97.5	-686.6	117	NC	3571.3	-679.6	177	SEG43	443.7	679.6
58	ICAS	-32.5	-686.6	118	NC	3519.1	-679.6	178	SEG44	391.5	679.6
59	BS0	32.5	-686.6	119	COM11	3466.9	-679.6	179	SEG45	339.3	679.6
60	VSS1	97.5	-686.6	120	COM10	3415.1	-679.6	180	SEG46	287.1	679.6

Pad no.	Signal	X-pos	Y-pos
181	SEG47	234.9	679.6
182	SEG48	182.7	679.6
183	SEG49	130.5	679.6
184	SEG50	78.3	679.6
185	SEG51	26.1	679.6
186	SEG52	-26.1	679.6
187	SEG53	-78.3	679.6
188	SEG54	-130.5	679.6
189	SEG55	-182.7	679.6
190	SEG56	-234.9	679.6
191	SEG57	-287.1	679.6
192	SEG58	-339.3	679.6
193	SEG59	-391.5	679.6
194	SEG60	-443.7	679.6
195	SEG61	-495.9	679.6
196	SEG62	-548.1	679.6
197	SEG63	-600.3	679.6
198	SEG64	-652.5	679.6
199	SEG65	-704.7	679.6
200	SEG66	-756.9	679.6
201	SEG67	-809.1	679.6
202	SEG68	-861.3	679.6
203	SEG69	-913.5	679.6
204	SEG70	-965.7	679.6
205	SEG71	-1017.9	679.6
206	SEG72	-1070.1	679.6
207	SEG73	-1122.3	679.6
208	SEG74	-1174.5	679.6
209	SEG75	-1226.7	679.6
210	SEG76	-1278.9	679.6
211	SEG77	-1331.1	679.6
212	SEG78	-1383.3	679.6
213	SEG79	-1435.5	679.6
214	SEG80	-1487.7	679.6
215	SEG81	-1539.9	679.6
216	SEG82	-1592.1	679.6
217	SEG83	-1644.3	679.6
218	SEG84	-1696.5	679.6
219	SEG85	-1748.7	679.6
220	SEG86	-1800.9	679.6
221	SEG87	-1853.1	679.6
222	SEG88	-1905.3	679.6
223	SEG89	-1957.5	679.6
224	SEG90	-2009.7	679.6
225	SEG91	-2061.9	679.6
226	SEG92	-2114.1	679.6
227	SEG93	-2166.3	679.6
228	SEG94	-2218.5	679.6
229	SEG95	-2270.7	679.6
230	SEG96	-2322.9	679.6
231	SEG97	-2375.1	679.6
232	SEG98	-2427.3	679.6
233	SEG99	-2479.5	679.6
234	SEG100	-2531.7	679.6
235	SEG101	-2583.9	679.6
236	SEG102	-2636.1	679.6
237	SEG103	-2688.3	679.6
238	NC	-2740.5	679.6
239	NC	-2792.7	679.6
240	NC	-2844.9	679.6

Pad no.	Signal	X-pos	Y-pos
241	COM24	-2897.1	679.6
242	COM25	-2948.9	679.6
243	COM26	-3000.7	679.6
244	COM27	-3052.5	679.6
245	COM28	-3104.3	679.6
246	COM29	-3156.1	679.6
247	COM30	-3207.9	679.6
248	COM31	-3259.7	679.6
249	COM32	-3311.5	679.6
250	COM33	-3363.3	679.6
251	COM34	-3415.1	679.6
252	COM35	-3466.9	679.6
253	NC	-3519.1	679.6
254	NC	-3571.3	679.6



Pad 1,2,3,...->116

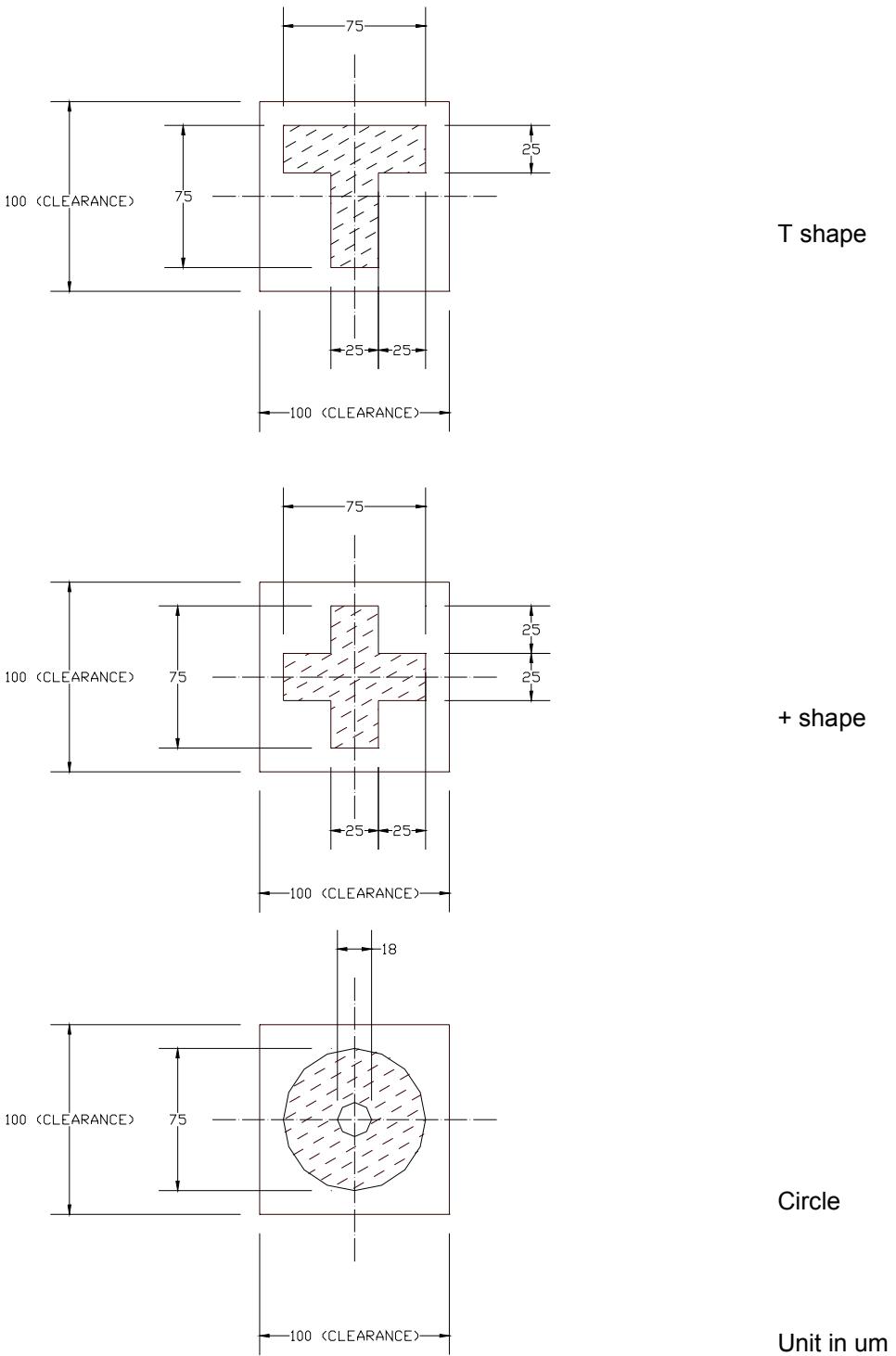
Gold Bumps face up

Die size	7.29mm x 1.56mm
Die height	475 +/- 25um

Bump height	Nominal 18um
Bump size	
Pad 1-14, 103-254	34um x 84um
Pad 15-102	42um x 70um

Alignment mark	
T shape	(-2392.0, 79.5)
+ shape	(2392.0, 79.5)
Circle	(-2677.0, -274.6)
	R37.5um, inner 18um

Figure 3 - SSD0300Z Alignment mark dimensions



6 PIN DESCRIPTION

CL

This pin is the system clock input. When internal clock is enabled, this pin should be left open. The internal clock is output from this pin. When internal oscillator is disabled, this pin receives display clock signal from external clock source.

CLS

This is the internal clock enable pin. When it is pulled HIGH, internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.

BS0, BS1, BS2

These are MCU interface input selection pins. See the following table for selecting different interfaces:

	6800-parallel interface	8080-parallel interface	Serial interface	I ² C Interface
BS0	0	0	0	0
BS1	0	1	0	1
BS2	1	1	0	0

CS#

This pin is the chip select input. The chip is enabled for MCU communication only when CS# had been pulled low. Tie to L for I²C mode application.

RES#

This is a reset signal input pin. When it is pulled LOW, initialization of the chip is executed.

D/C (SA0)

This is the Data/Command control pin. When it is pulled HIGH, the input at D₇-D₀ is treated as display data. When it is pulled LOW, the input at D₇-D₀ is transferred to the command registers. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams.
In I²C mode, this pin act as SA0 for slave address selection

R/W (WR#)

This is a MCU interface input pin. When 6800-series Parallel Interface mode is selected, this pin is used as Read/Write (R/W#) selection input. Pull this pin to HIGH for read mode and pull it to LOW for write mode.

When 8080-series Parallel Interface mode is selected, this pin is used as Write (WR#) selection input. Pull this pin to LOW for write mode. Data write operation is initiated when this pin is pulled LOW and the CS# is pulled LOW.

When I²C Interface mode is selected, this pin is tied to LOW.

E (RD#)

This is a MCU interface input pin. When 6800-series Parallel Interface is selected, this pin is used as Enable (E) signal. Read/Write operation is initiated when this pin is pulled HIGH and the CS# pin is pulled LOW. When 8080-series Parallel Interface is selected, this pin is used to receive the Read Data (RD#) signal. Data read operation is initiated when this pin is pulled LOW and CS# pin is pulled LOW. When I²C Interface mode is selected, this pin is tied to LOW.

D₇-D₀

These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial interface mode is selected, D₁ will be the serial data input, SD_{IN}, and D₀ will be the serial clock input, SCLK.

When I²C mode is selected, D₂ and D₁ should be tied together and serve as SDA_{OUT}, SDA_{IN} and D₀ is the serial clock input, SCL.

V_{DD}

This is a voltage supply pin. It must be connected to external source.

V_{SS}

This is a ground pin. It also acts as a reference for the logic pins and the OLED driving voltages. It must be connected to external ground.

BGGND

This is a ground pin for analog circuits. It must be connected to external ground

V_{CC}

This is the most positive voltage supply pin of the chip. It should be supplied externally.

V_{REF}

This is a voltage reference pin for pre-charge voltage in driving OLED device. Voltage should be set to match with the OLED driving voltage in current drive phase. It can either be supplied externally or by connecting to VCC.

I_{REF}

This is a segment current reference pin. A resistor should be connected between this pin and V_{SS}. Set the current at 10uA.

V_{COMH}

This is an input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.

V_{DDB}

This is a voltage supply pin. It should be connected to V_{DD}.

V_{SSB}

This is a ground pin. It should be connected to V_{SS}.

GDR, RESE, VBREF, FB

These are reserved pins. No connection necessary and should be left open.

COM0-COM47

These pins provide the Common switch signals to the OLED panel. These pins are in high impedance state when display is OFF.

SEG0-SEG103

These pins provide the OLED segment driving signals. These pins are in high impedance stage when display is off.

GPIO0, GPIO1 and ICAS

These are reserved pins. No connection should be made for these pins and left float individually.

VSL

This is a segment voltage reference pin. This pin should be connected to V_{SS} externally.

VCL

This is a common voltage reference pin. This pin should be connected to V_{SS} externally.

V_{DD1}

V_{DD1} is internally connected to V_{DD}. They are for pull high purpose for the neighboring pins if necessary.

V_{DD1} can be left open when it is not used.

Main power supply should connect to V_{DD} pins.

V_{SS1}

V_{SS1} is internally connected to V_{SS}. They are for pull low purpose for the neighboring pins if necessary.

V_{SS1} can be left open when it is not used.

Main power supply should connect to V_{SS} pin.

NC

These are reserved pins and should not be connected. Do not group or short NC pins.

7 MPU INTERFACES DESCRIPTIONS

MPU I²C Interface

The I²C communication interface consists of slave address bit SA0, I²C-bus data signal SDA (D₂ for output and D₁ for input) and I²C-bus clock signal SCL (D₀). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)

SSD0300 has to recognize the slave address before transmitting or receiving any information by the I²C-bus. The device will respond to the slave address following by the slave address bit ("SA0" bit) and the read/write select bit ("R/W#" bit) with the following byte format,

b₇ b₆ b₅ b₄ b₃ b₂ b₁ b₀
0 1 1 1 1 0 SA0 R/W#

"SA0" bit provides an extension bit for the slave address. Either "0111100" or "0111101", can be selected as the slave address of SSD0300.

"R/W#" bit is used to determine the operation mode of the I²C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

b) I²C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA. If SDA in is connected to the "SDA out", the device becomes fully I²C bus compatible.

It should be noticed that the ITO track resistance and the pulled-up resistance at "SDA" pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in "SDA".

The "SDA out" pin may be disconnected from the "SDA in" pin. With such arrangement, the acknowledgement signal will be ignored in the I²C-bus.

c) I²C-bus clock signal (SCL)

The transmission of information in the I²C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

I²C-bus Write data and read register status

The I²C-bus interface gives access to write data and command into the device. Please refer to Figure 4 for the write mode of I²C-bus in chronological order.

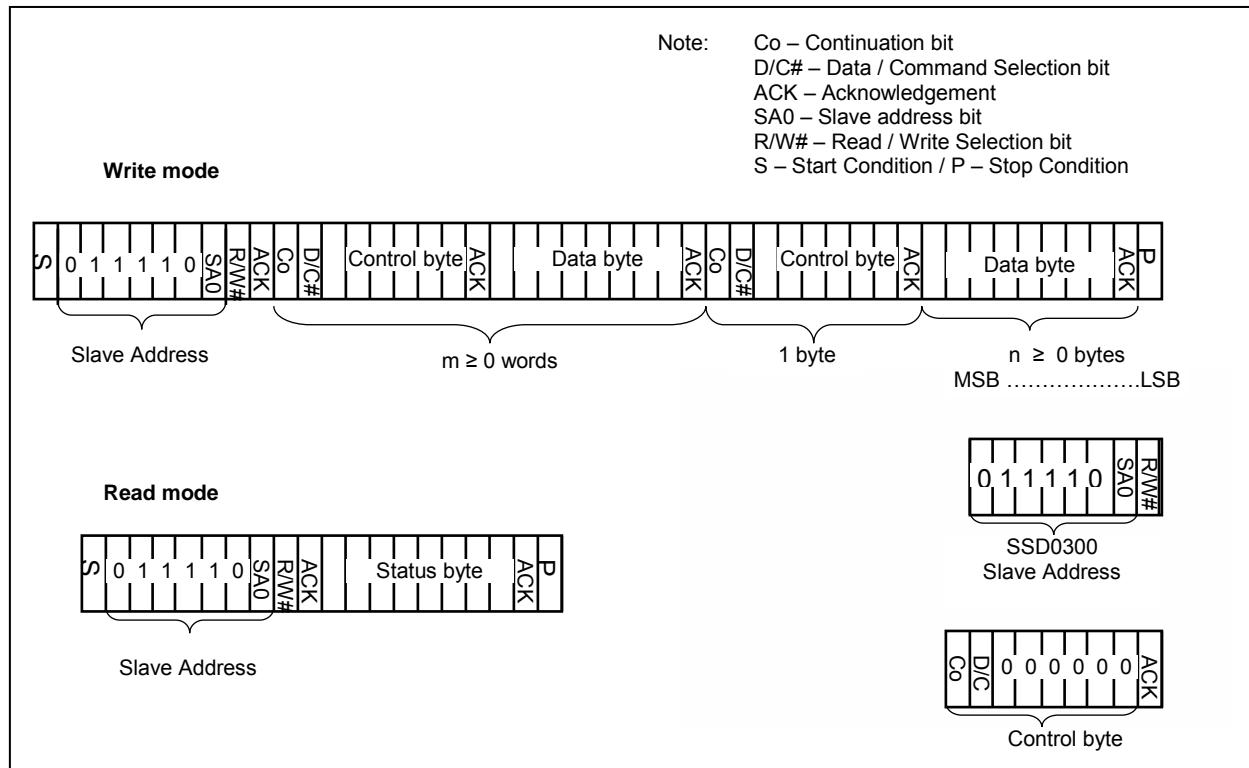


Figure 4 - I²C-bus data format

Write mode for I²C

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 5. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD0300, the slave address is either "b0111100" or "b0111101" by changing the SA0 to HIGH or LOW.
- 3) The write mode is established by setting the R/W# bit to logic "0".
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 6 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six "0" 's.
 - a. If the Co bit is set as logic "0", the transmission of the following information will contain data bytes only.
 - b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic "0", it defines the following data byte as a command. If the D/C# bit is set to logic "1", it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 6) Acknowledge bit will be generated after receiving each control byte or data byte.
- 7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 5. The stop condition is established by pulling the "SDA in" from LOW to HIGH while the "SCL" stays HIGH.

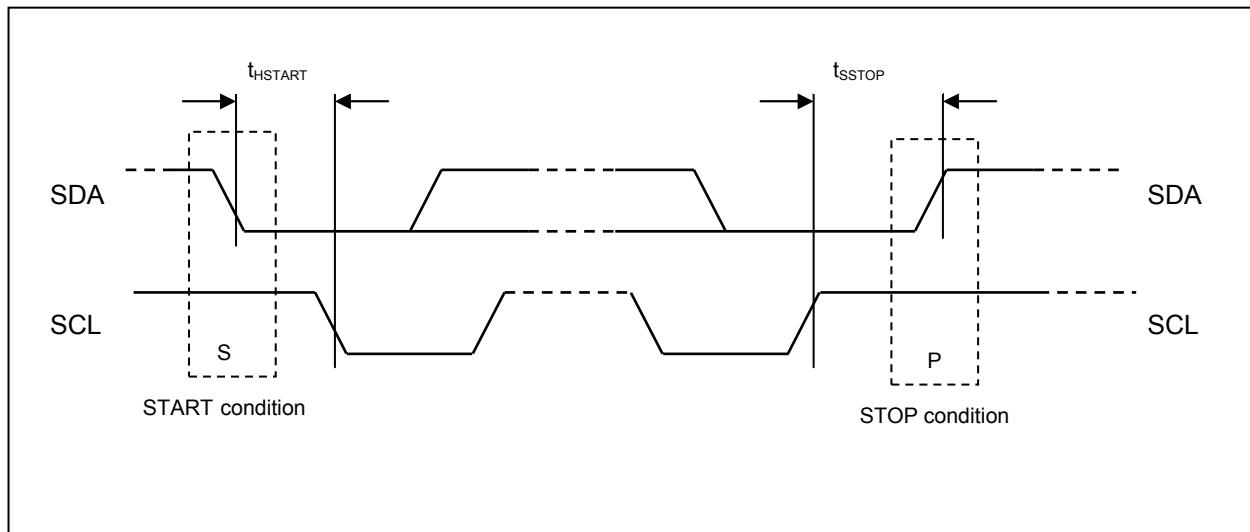


Figure 5 - Definition of the Start and Stop Condition

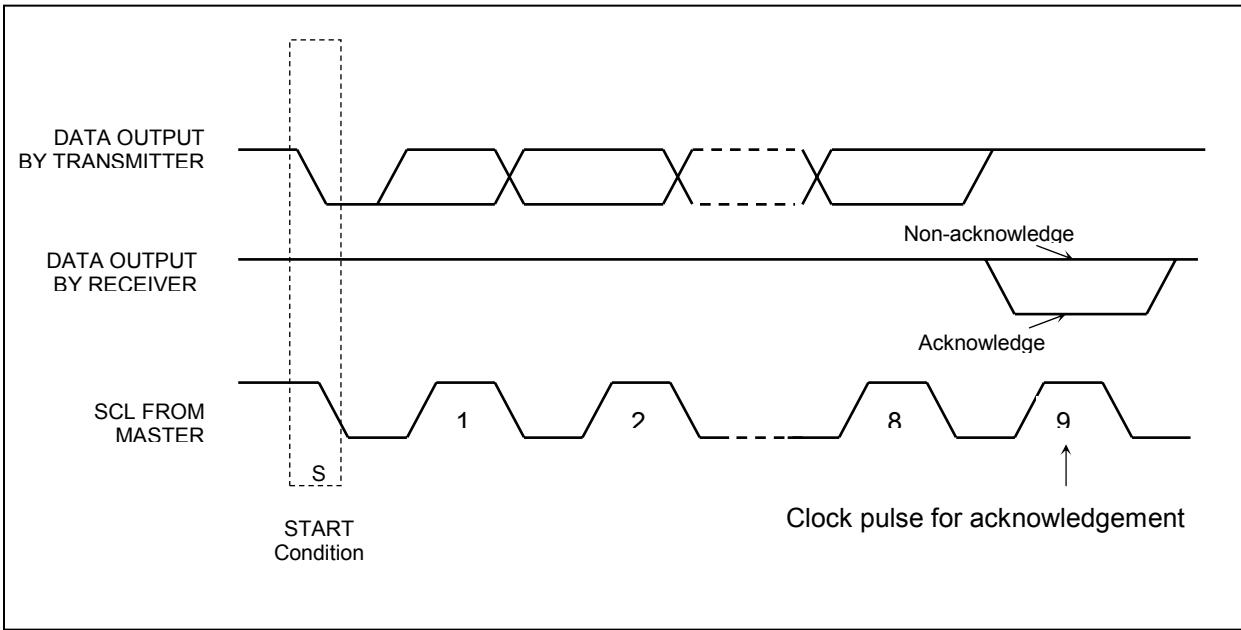


Figure 6 - Definition of the acknowledgement condition

Please be noted that the transmission of the data bit has some limitations.

1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the "HIGH" period of the clock pulse. Please refer to the Figure 7 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

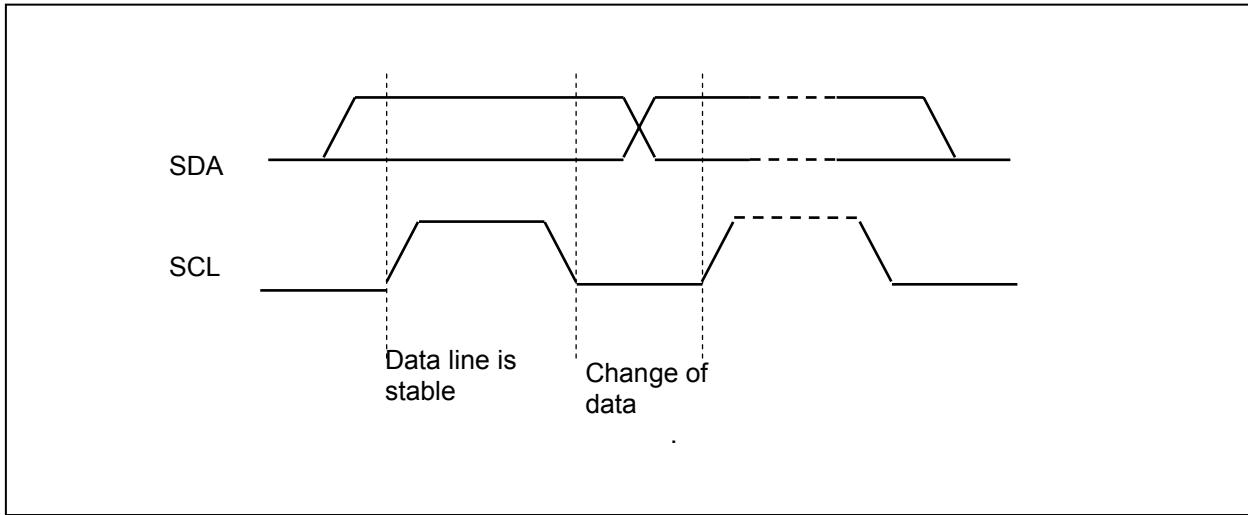


Figure 7 - Definition of the data transfer condition

Read mode for I²C (Read status register)

- 1) The master device firstly initiates the data communication by a start condition. The definition of the start condition is shown in Figure 5.
- 2) The slave address is following the start condition for recognition use. For the SSD0300, the slave address is either “b0111100” or “b0111101”.
- 3) The read mode is established by setting R/W# bit to logic “1”. The read mode allows the MCU to monitor the internal status of the chip.
- 4) An acknowledgement signal will be generated after sending one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 6 for the graphical representation of the acknowledge signal.
- 5) The status of the register will be read at the next status byte. Please refer to the Read Command Table for the explanation of the status byte.
- 6) The read mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 5.

MPU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D_7-D_0), R/W (WR#), E (RD#), D/C, CS#. When the R/W (WR#) pin is pulled HIGH, Read operation from the Graphic Display Data RAM (GDDRAM) or the status register occurs. When the R/W (WR#) pin is pulled LOW, Write operation to Display Data RAM or Internal Command Registers occurs, depending on the status of D/C input. The E (RD#) input serves as data latch signal (clock) when HIGH provided that CS# is LOW. Refer to Parallel Interface Timing Diagram of 6800-series microprocessors.

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed, which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8 below.

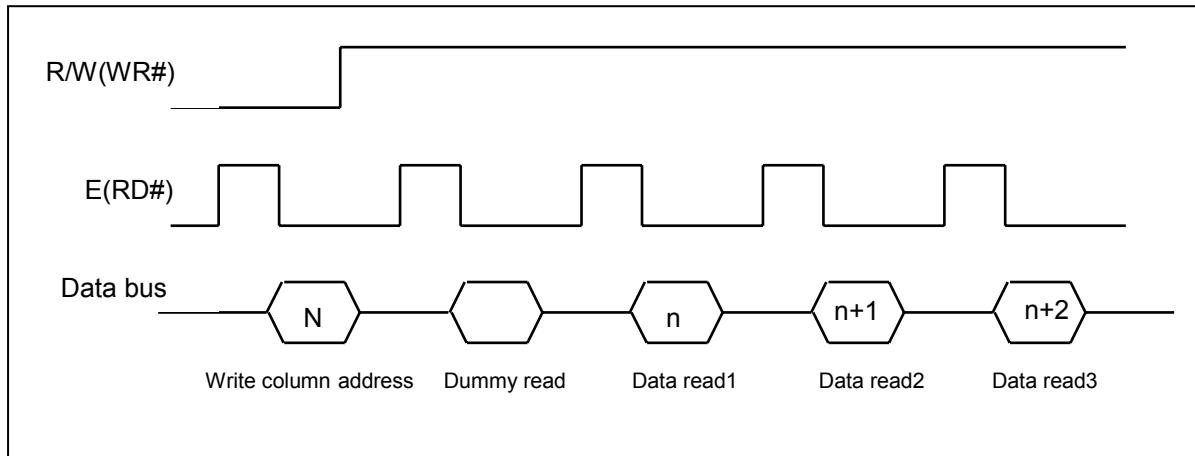


Figure 8 - Display data read back procedure - insertion of dummy read

MPU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D_7-D_0), E (RD#), R/W(WR#), D/C, CS#. The E (RD#) input serves as data read latch signal (clock) when it is low, and provided that CS# is low. Display data or status register read is controlled by D/C.

R/W (WR#) input serves as data write latch signal (clock) when it is high and provided that CS# is low. Display data or command register write is controlled by D/C. Refer to Parallel Interface Timing Diagram of 8080-series microprocessor. Similar to 6800-series interface, a dummy read is also required before the first actual display data read.

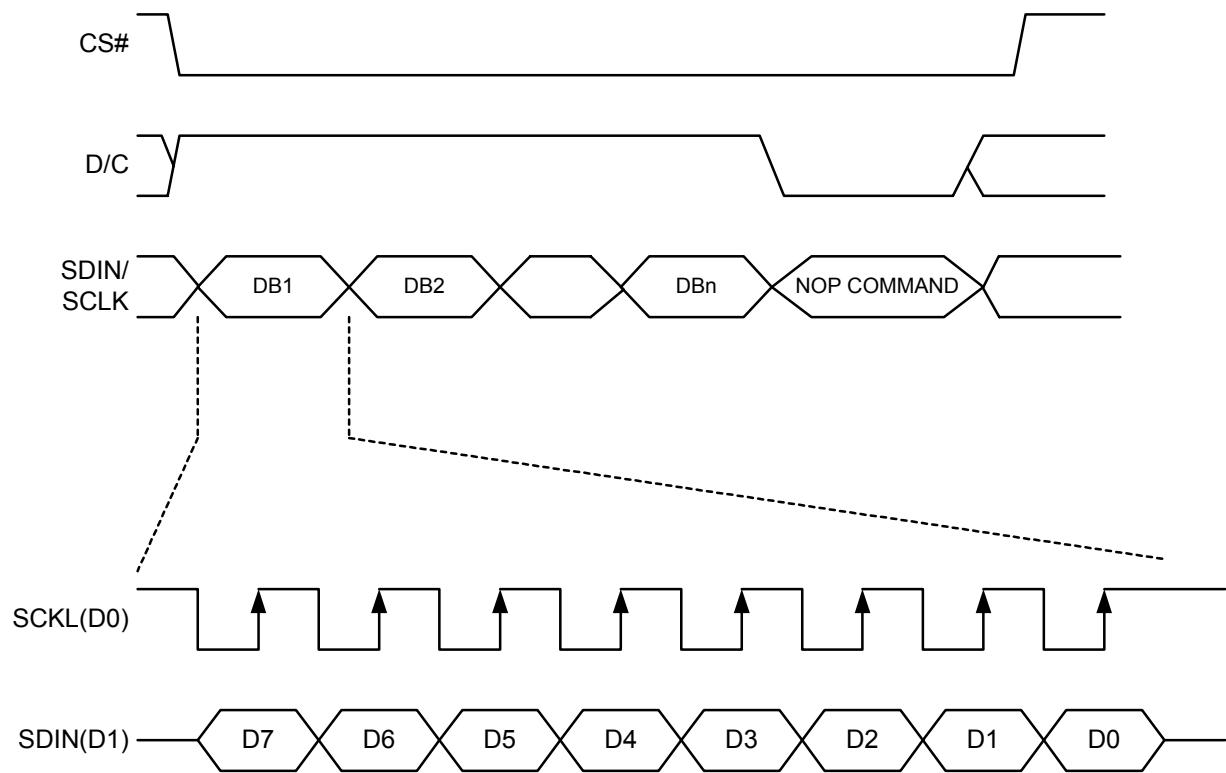
MPU Serial Interface

The serial interface consists of serial clock SCLK, serial data SDIN, D/C, CS#. In SPI mode, D0 acts as SCLK and D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W can be connected to an external ground.

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D₇, D₆, ... D₀. D/C is sampled on every eighth clock and the data byte in the shift register is written to the Display Data RAM or command register in the same clock.

During data writing, an additional NOP command should be inserted before the CS# goes high (Refer to Figure 9).

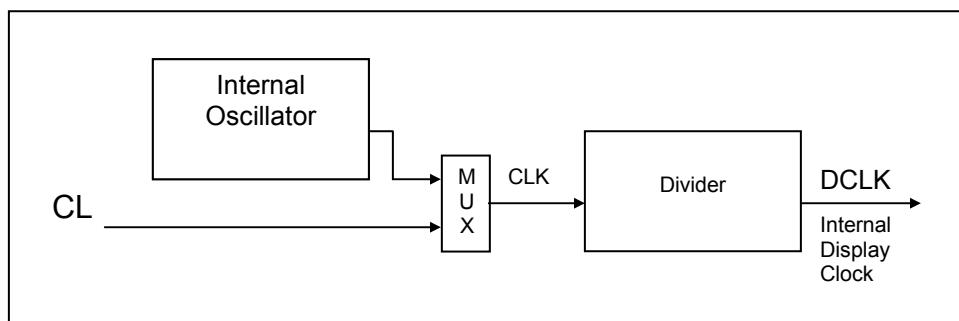
Figure 9 – Display data write procedure in SPI mode



8 FUNCTIONAL BLOCK DESCRIPTIONS

Oscillator Circuit and Display Time Generator

Figure 10 - Oscillator Circuit



This module is an On-Chip low power RC oscillator circuitry (Figure 10). The oscillator generates the clock for the Display Timing Generator.

Reset Circuit

When RES# input is low, the chip is initialized with the following status:

1. Display is OFF
2. 104x48 Display Mode
3. Normal segment and display data column address and row address mapping (SEG0 mapped to column address 00H and COM0 mapped to row address 00H)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 80H
9. Internal DC/DC booster is enable

Command Decoder and Command Interface

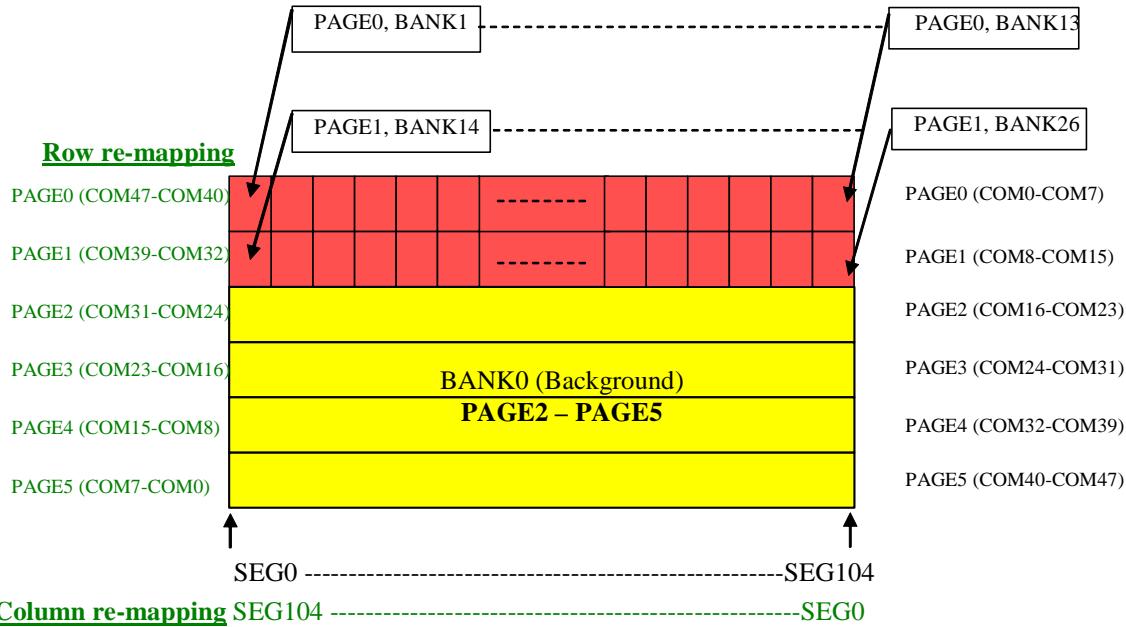
This module determines whether the input data is interpreted as data or command. When the D/C# pin is pulled HIGH, the inputs at D₇-D₀ are interpreted as data and will be written to Graphic Display Data RAM (GDDRAM). When it is pulled LOW, the inputs at D₇-D₀ are interpreted as command, they will be decoded and be written to the corresponding command registers.

Graphic Display Data RAM (GDDRAM)

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 104 x 48 bits and the RAM is divided into six pages, from PAGE0 to PAGE5, as shown in Figure 11. In GDDRAM, PAGE0 and PAGE1 are belonged to area color section with resolution 104x 16. PAGE2 to PAGE5 are used for monochrome 104x 32 dot matrix display.

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. For vertical scrolling of the display, an internal register storing display start line can be set to control the portion of the RAM data to be mapped to the display.

Figure 11 - GDDRAM pages structure of SSD0300

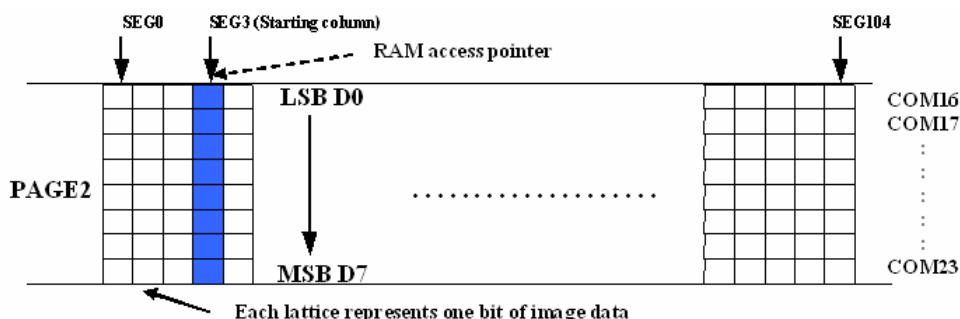


In normal display data RAM read or write mode, the following steps are required to define the starting RAM access pointer location:

- Set the page address of the target display location by command B0h ~ B5h.
- Set the lower column address of pointer by command 00h~0Fh.
- Set the upper column address of pointer by command 10h~1Fh.

For example, if the page address is set to B2h, lower column address is 03h and upper column address is 00h, then that means the starting column is SEG3 of PAGE2. The RAM access pointer is located as shown in Figure 12. The input data byte will be written into RAM position of column 3.

Figure 12 - Example of GDDRAM access location setting (No row re-mapping & column-remapping)



When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row. GDDRAM column address pointer will be increased by one column automatically after each data access. If the current column address pointer points to SEG104, it will point to SEG0 in the same page after the data access. Users have to set the new page address, new lower and upper column address in order to access the next page RAM content.

Current Control and Voltage Control

This block is used to derive the incoming power sources into the different levels of internal use voltage and current. V_{CC} and V_{DD} are external power supplies. V_{REF} is reference voltage, which is used to derive driving voltage for segments and commons. I_{REF} is a reference current source for segment current drivers.

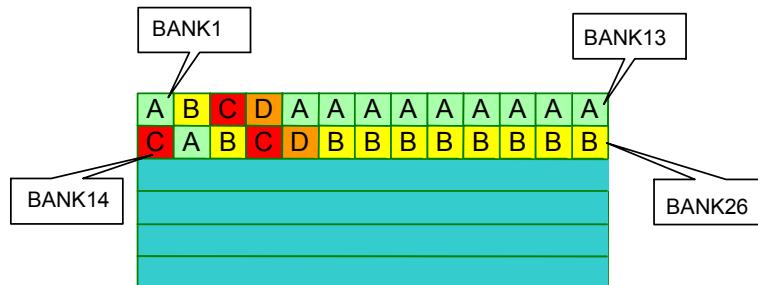
Segment Drivers/Common Drivers

Segment drivers deliver 104 current sources to drive OLED panel. The driving current can be adjusted from 0 to 320uA with 256 steps. Common drivers generate voltage scanning pulses.

Area Colour Decoder

The 104x48 display matrix is divided into six pages. PAGE0 and PAGE1 of the display are divided into 26 banks. Each bank comprises of a display area of 8x8 pixels. Each bank can be programmed to any one of the 4 colours (colour A, B, C, D) as the example shown in Figure 13. Detailed operation can be referred to the Command Table.

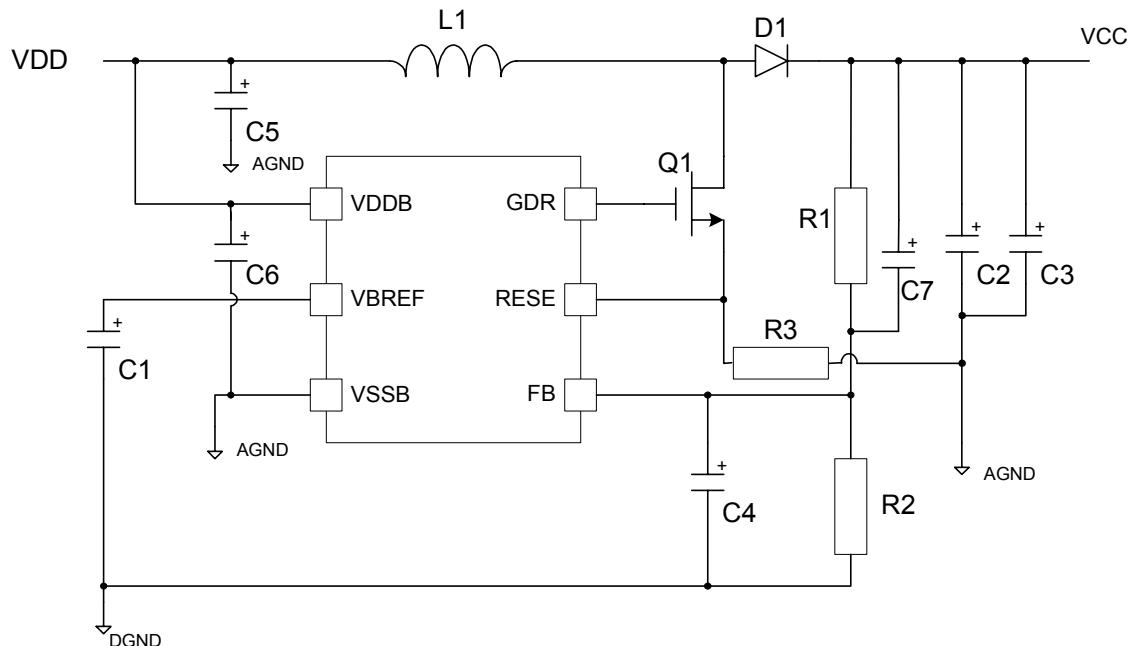
Figure 13 - Example of area color assignment on a 104x48 OLED panel



DC-DC Voltage Converter

It is a switching voltage generator circuit, designed for handheld applications. In SSD0300, internal DC-DC voltage converter accompanying with an external application circuit (shown in below figure) can generate a high voltage supply V_{CC} from a low voltage supply input V_{DD} . V_{CC} is the voltage supply to the OLED driver block. Below application circuit is an example for the input voltage of 3V V_{DD} to generate V_{CC} of 12V @0mA ~ 20mA application.

Figure 14 - DC-DC voltage converter circuit



Remark:

1. VSSB is tied to VSS on SSD0300T3 package.
2. L1, D1, Q1, C5 should be grouped closed together on PCB layout.
3. R1, R2, C1, C4 should be grouped closed together on PCB layout.
4. The VCC output voltage level can be adjusted by R1and R2, the reference formula is:

$$V_{CC} = 1.2 \times (R_1 + R_2) / R_2$$

The value of $(R_1 + R_2)$ should be between 500k to 1M Ohm.

Table 3 - Passive component selection:

Components	Typical Value	Remark
L1	Inductor, 10µH	1A
D1	Schottky diode	1A, 25V e.g. 1N5822, BAT54 [Philips Semiconductors]
Q1	MOSFET	N-FET with low $R_{DS(on)}$ and low V _{th} voltage. e.g. MGSF1N02LT1 [ON SEMI]
R1, R2	Resistor	1%, 1/10W
R3	Resistor, 1.2Ω	1%, 1/2W
C1	Capacitor, 1µF	16V
C2	Capacitor, 6.8µF	Low ESR, 25V
C3	Capacitor, 1µF	16V
C4	Capacitor, 10nF	16V
C5	Capacitor, 1 ~ 10 µF	16V
C6	Capacitor, 0.1 ~ 1µF	16V
C7	Capacitor, 15nF	16V

9 COMMAND TABLE

Table 4 - Command table

(D/C =0, R/W(WR#)=0, E(RD#=1)

Note: commands marked with “**” are compatible to SSD1301

D/C	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	00-0F	0	0	0	0	X ₃	X ₂	X ₁	X ₀	Set Lower Column Address **	Set the lower nibble of the column address register using X ₃ X ₂ X ₁ X ₀ as data bits. The initial display line register is reset to 0000b after POR.
0	10-1F	0	0	0	1	X ₃	X ₂	X ₁	X ₀	Set Higher Column Address **	Set the higher nibble of the column address register using X ₃ X ₂ X ₁ X ₀ as data bits. The initial display line register is reset to 0000b after POR.
0	2F	0	0	1	0	1	1	1	1	Activate horizontal scroll	Start horizontal scrolling
0	2E	0	0	1	0	1	1	1	0	Deactivate horizontal scroll	Stop horizontal scrolling
0	26	0	0	1	0	0	1	1	0	Horizontal scroll setup	A[3:0] Set the number of column scroll per step Valid value: 0001b to 1000b
0	A[3:0]	*	*	*	*	*	A ₃	A ₂	A ₁	A ₀	B[2:0] Define start page address
0	B[2:0]	*	*	*	*	*	*	B ₂	B ₁	B ₀	C[1:0] Set time interval between each scroll step in terms of frame frequency
0	C[1:0]	*	*	*	*	*	*	C ₁	C ₀		00b – 12 frames
0	D[2:0]	*	*	*	*	*	*	D ₂	D ₁	D ₀	01b – 64 frames
											10b – 128 frames
											11b – 256 frames
											D[2:0] Define end page address
											Set the value of D[2:0] larger or equal to B[2:0]
0	40-6F	0	1	X ₅	0	X ₃	X ₂	X ₁	X ₀	Set Display Start Line	Set display RAM display start line register from 0-47 using X ₅ X ₃ X ₂ X ₁ X ₀ . Display start line register is reset to 000000 during POR.
0	81	1	0	0	0	0	0	0	1	Set Contrast Control Register **	Double byte command to select 1 out of 256 contrast steps. Contrast increases as the value increases. (POR = 80h)
0	A[7:0]	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
0	X[5:0]	*	*	X ₅	X ₄	X ₃	X ₂	X ₁	X ₀	Set Look Up Table (LUT) for area colour	Set current drive pulse width of Bank 0, Colour A, B and C. Bank 0: X[5:0] = 0...47; for pulse width set to 1 ~ 64 clk
0	A[5:0]	*	*	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
0	B[5:0]	*	*	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		Colour A: A[5:0] same as above
0	C[5:0]	*	*	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀		Colour B: B[5:0] same as above
											Colour C: C[5:0] same as above
											Note: colour D pulse width is fixed at 64 clks pulse.

D/C	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	92	1	0	0	1	0	0	1	0	Set bank colour of for bank 1-13 (Page 0)	A[1:0] : 00, 01, 10, or 11 for Colour = A, B, C or D of bank 1
0	A[7:0]	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		A[3:2] : 00, 01, 10, or 11 for Colour = A, B, C or D of bank 2
0	B[7:0]	B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		:
0	C[7:0]	C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀		:
0	D[1:0]	*	*	*	*	*	*	D ₁	D ₀		D[1:0]: 00, 01, 10, or 11 for Colour = A, B, C or D of bank 13
0	93	1	0	0	1	0	0	1	1	Set bank colour of for bank 14-26 (Page 1)	A[1:0] : 00, 01, 10, or 11 for Colour = A, B, C or D of bank 14
0	A[7:0]	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		A[3:2] : 00, 01, 10, or 11 for Colour = A, B, C or D of bank 15
0	B[7:0]	B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		:
0	C[7:0]	C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀		D[1:0]: 00, 01, 10, or 11 for Colour = A, B, C or D of bank 26
0	A0~A1	1	0	1	0	0	0	0	X ₀	Set Segment Re-map **	X ₀ =0:column address 0 is mapped to SEG0 (POR) X ₀ =1:column address 103 is mapped to SEG0
0	A4~A5	1	0	1	0	0	1	0	X ₀	Set Entire Display On/Off **	X ₀ =0:normal display (POR) X ₀ =1:entire display on
0	A6~A7	1	0	1	0	0	1	1	X ₀	Set Normal/Inverse Display **	X ₀ =0:normal display (POR) X ₀ =1:inverse display
0	A8	1	0	1	0	1	0	0	0	Set Multiplex Ratio **	The next command, A[5:0] determines multiplex ratio N from 16MUX-48MUX, POR= 48MUX
0	A[5:0]	*	*	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
0	AA	1	0	1	0	1	0	1	0	NOP	Reserved, do not use
0	AB	1	0	1	0	1	0	1	1	NOP	Reserved, do not use
0	AD A[2:0]	1	0	1	0	1	1	0	X ₁ X ₀	Set DC-DC on/off	X ₀ : 1 DC-DC will be turned on when display on (POR) 0 DC-DC is disable X ₁ =0, Select external VCOMH voltage supply at Display ON X ₁ =1, Select internal VCOMH regulator at Display ON (POR)
0	AE~AF	1	0	1	0	1	1	1	X ₀	Set Display On/Off **	X ₀ =0:turns off OLED panel (POR) X ₀ =1:turns on OLED panel
0	B0~B5	1	0	1	1	0	X ₂	X ₁	X ₀	Set Page Address **	Set GDDRAM Page Address (0~5) for read/write using X ₂ X ₁ X ₀
0	C0/C8	1	1	0	0	X ₃	*	*	*	Set COM Output Scan Direction **	X ₃ =0:normal mode (POR) Scan from COM 0 to COM [N-1] X ₃ =1:remapped mode. Scan from COM [N-1] to COM0 Where N is the Multiplex ratio.

D/C	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	D0-D1	1	1	0	1	0	0	0	X ₀	Reserved	Reserved, do not use
0	D3 A[5:0]	1 *	1 *	0 A ₅	1 A ₄	0 A ₃	0 A ₂	1 A ₁	1 A ₀	Set Display Offset **	Set vertical scroll by COM from 0-47. The value is reset to 00H after POR.
0	D5 A[3:0] A[7:4]	1 * A ₇	1 * A ₆	0 * A ₅	1 * A ₄	0 A ₃ * A ₂	1 A ₂ * A ₁	0 A ₁ * A ₀	1 A ₀	Set Display Clock Divide Ratio/Oscillator Frequency	The lower nibble of the next command sets the divide ratio of the display clocks (dclk). The ratio is the value of A[3:0] +1 Divide ratio= 1-16, POR value is 0000b (divide by 1). The higher nibble of the next command sets the Oscillator Frequency. Oscillator Frequency increases with the value of A[7:4] and vice versa.
0	D8	1 0	1 0	0 X ₅	1 X ₄	1 0	0 X ₂	0 0	0 X ₀	Set area colour mode on/off & low power display mode	X ₅ X ₄ = 00 (POR) : mono mode X ₅ X ₄ = 11" Area Colour enable X ₂ =0 and X ₀ =0: Normal (POR) power mode X ₂ =1 and X ₀ =1: Set low power save mode
0	D9 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	1 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Pre-charge period	A[3:0] Phase 1 period of up to 15 dclk clocks [POR=2h] A[7:4] Phase 2 period of up to 15 dclk clocks [POR=2h]
0	DA 02/22	1 0	1 0	0 0	1 X ₄	1 0	0 0	1 1	0 0	Set COM pins hardware configuration	X ₄ =0, Sequential COM pin configuration (i.e. COM23, 22, ..., 2, 0 ; SEG0-103; COM24,25,...46,47) X ₄ =1(POR), Alternative COM pin configuration (i.e. COM46,44,...2, 0; SEG0 -103; COM1,3,5...,45,47)
0	DB A[6:0]	1 * A ₆	1 A ₅	0 A ₅	1 A ₄	1 A ₃	0 A ₂	1 A ₁	1 A ₀	Set VCOMH	A[6:0] 0000000 0.43*Vref 0111111 0.83*Vref (POR) 1111111 1.0*Vref
0	E2	1	1	1	0	0	0	1	0	Reserved	Reserved
0	E3	1	1	1	0	0	0	1	1	NOP **	Command for No Operation

Note: Remark “**” stands for “Don’t Care”

Table 5 - Read command table

(D/C=0, R/W(WR#=1, E(RD#=1 for 6800 or E(RD#=0 for 8080)

Bit Pattern	Command	Description
D ₇ D ₆ D ₅ D ₄ D ₃ D ₂ D ₁ D ₀	Status Register Read *	D ₇ : “1” for Command lock D ₆ : “1” for display OFF / “0” for display ON D ₅ : Reserve D ₄ : Reserve D ₃ : Reserve D ₂ : Reserve D ₁ : Reserve D ₀ : Reserve

Note: Patterns other than that given in Command Table are prohibited to enter to the chip as a command; otherwise, unexpected result will occur.

Data Read / Write

To read data from the GDDRAM, input High to R/W(WR#) pin and D/C# pin for 6800-series parallel mode, Low to E(RD#) pin and High to D/C pin for 8080-series parallel mode. No data read is provided for serial mode.

In normal data read mode, GDDRAM column address pointer will be increased by one automatically after each data read. However, no automatic increase will be performed in read-modify-write mode. Also, a dummy read is required before the first data read. See Figure 8 in Functional Block Description.

To write data to the GDDRAM, input Low to R/W#(WR#) pin and High to D/C# pin for 6800-series parallel mode AND 8080-series parallel mode. For serial interface mode, it is always in write mode. GDDRAM column address pointer will be increased by one automatically after each data write.

Table 6 - Address increment table (Automatic)

D/C#	R/W(WR#)	Comment	Address Increment
0	0	Write Command	No
0	1	Read Status	No
1	0	Write Data	Yes
1	1	Read Data	Yes*1

*1. If read-data command is issued in read-modify-write mode, address increase is not applied.

10 COMMAND DESCRIPTIONS

Set Lower Column Address

This command specifies the lower nibble of the 8-bit column address of the display data RAM. The column address will be incremented by each data access after it is pre-set by the MCU.

Set Higher Column Address

This command specifies the higher nibble of the 8-bit column address of the display data RAM. The column address will be incremented by each data access after it is pre-set by the MCU.

Activate Horizontal Scroll

Start motion of horizontal scrolling. This command should only be issued after Horizontal scroll setup parameters are defined.

The following actions are prohibited after the horizontal scroll is activated

1. RAM access (Data write or read)
2. Changing horizontal scroll setup parameters

The SSD0300 horizontal scroll is designed for 96 columns scrolling only. The 8 remaining columns are reserved for computation during scrolling and should be left open.

Figure 15 - Horizontal scroll direction

Remap Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	SEG7	SEG8	SEG9	SEG10	SEG11	:	:	SEG92	SEG93	SEG94	SEG95	SEG96	SEG97	SEG98	SEG99	SEG100	SEG101	SEG102	SEG103
A0	A	B	C	D	E	F	G	H	I	J	K	L	→	→	W	X	Y	Z	Invalid data							
A1	Invalid data								Z	Y	X	W	←	←	L	K	J	I	H	G	F	E	D	C	B	A

Scroll direction

Deactivate Horizontal Scroll

Stop motion of horizontal scrolling.

Horizontal Scroll Setup

This command consists of 5 consecutive bytes to set up the horizontal scroll parameters. It determines scroll direction, scrolling start page, end page and scrolling speed.

Before issuing this command, the horizontal scroll must be deactivated (2Fh). Otherwise, ram content may be corrupted.

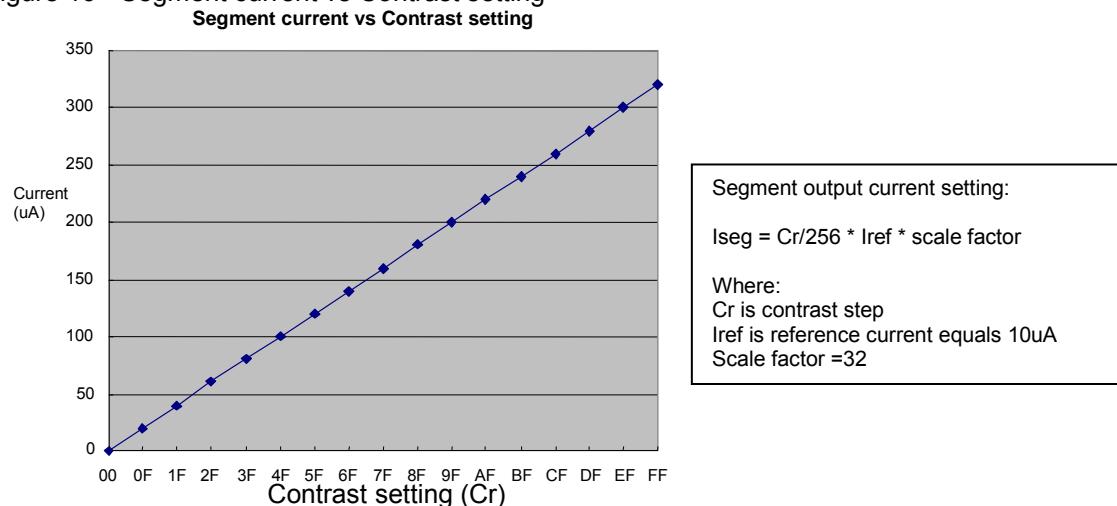
Set Display Start Line

This command is to set Display Start Line register to determine starting address of display RAM to be displayed by selecting a value from 0 to 47. With value equals to 0, D₀ of Page 0 is mapped to COM0. With value equals to 1, D₁ of Page0 is mapped to COM0. The display start line values of 0 to 47 are assigned to Page 0 to 7.

Set Contrast Control Register

This command is to set Contrast Setting of the display. The chip has 256 contrast steps from 00 to FF. The segment output current increases as the contrast step value increases. See Figure 6 below.

Figure 16 - Segment current vs Contrast setting



Set Look Up Table (LUT) for area colour

SSD0300 provides 4 colour (pulse width) settings - Colour A, B, C and D. The colour intensity (or grey scale) is defined by the current drive pulse width. The pulse width of colour A, B, C can be programmable from 1 to 64 DCLK* duration. The colour D is fixed at 64 DCLK pulse width. This colour setting has to be stored in the Look Up Table (LUT).

For the background colour, the colour intensity is defined by a variable X[5:0].

Set LUT command: 10010001
X[5:0]
A[5:0]
B[5:0]
C[5:0]

	Description	Number of DCLKs
Bank 0	Set background colour	X[5:0]
Colour A	Set Pulse Width A	A[5:0]
Colour B	Set Pulse Width B	B[5:0]
Colour C	Set Pulse Width C	C[5:0]
Colour D	Pulse width D is fixed to 64 DCLK	64 (fixed)

DCLK: Internal Display Clock

Set bank colour of bank 1-13 (Page 0) and bank colour of bank 14-26 (Page 1)

Next step is to define the colour of each display area. The 104x48 display matrix is divided into 8 pages of 8 commons per pages. The first two pages, page 0 and page 1, are divided into 32 banks: Each bank comprise of a display area of 8x8 pixels. Each bank can be programmable to any 1 of the 4 colour (A, B, C, D). User can use 92h and 93h command for the bank colour setting. Note: Only applicable in colour mode.

Set Segment Re-map

This command changes the mapping between the display data column address and segment driver. It allows flexibility in OLED module design. Refer to Command Table.

Set Entire Display On/Off

This command forces the entire display to be “ON” regardless of the contents of the display data RAM. This command has priority over normal/reverse display. This command will be used with “Set Display ON/OFF” command to form a compound command for entering power save mode.

Set Normal/Inverse Display

This command sets the display to be either normal/inverse. In normal display, a RAM data of 1 indicates an “ON” pixel while in inverse display; a RAM data of 0 indicates an “ON” pixel.

Set Multiplex Ratio

This command switches default 47 multiplex mode to any multiplex ratio from 2 to 47. The output pads COM0-COM47 will be switched to corresponding COM signal.

Set Display On/Off

This command turns the display on or off. When the display is off, the segment and common output are in high impedance state.

Set Page Address

This command positions the page address from 0 to 5 in GDDRAM. Refer to Command Table.

Set COM Output Scan Direction

This command sets the scan direction of the COM output allowing layout flexibility in OLED module design. In addition, the display will have immediate effect once this command is issued. That is, if this command is sent during normal display, the graphic display will be vertically flipped.

Set Display Offset

This is a double byte command. The next command specifies the mapping of display start line (it is assumed that COM0 is the display start line, display start line register equals to 0) to one of COM0-47.

For example, to move the COM16 towards the COM0 direction for 16 lines, the 6-bit data in the second byte should be given by 010000. To move in the opposite direction by 16 lines, the 6-bit data should be given by (48 – 16) and so the second byte should be 100000.

Hardware pin name	Output								Set MUX ratio(A8)
	48	48	48	40	40	40	32		
	Remap	Remap	Remap	Remap	Remap	Remap	Remap		
	0	8	0	0	8	0	8		
0	0	8	0	0	0	8	16	Display start line (40 - 7F)	
COM0	Row47	Ram47	Row7	Ram7	Row47	Ram7	-	Row7	Ram23
COM1	Row46	Ram46	Row6	Ram6	Row46	Ram6	-	Row6	Ram22
COM2	Row45	Ram45	Row5	Ram5	Row45	Ram5	-	Row5	Ram21
COM3	Row44	Ram44	Row4	Ram4	Row44	Ram4	-	Row4	Ram20
COM4	Row43	Ram43	Row3	Ram3	Row43	Ram3	-	Row3	Ram19
COM5	Row42	Ram42	Row2	Ram2	Row42	Ram2	-	Row2	Ram18
COM6	Row41	Ram41	Row1	Ram1	Row41	Ram1	-	Row1	Ram17
COM7	Row40	Ram40	Row0	Ram0	Row40	Ram0	-	Row0	Ram16
COM8	Row39	Ram39	Row47	Ram47	Row39	Ram47	Row39	RAM47	-
COM9	Row38	Ram38	Row46	Ram46	Row38	Ram46	Row38	RAM46	-
COM10	Row37	Ram37	Row45	Ram45	Row37	Ram45	Row37	RAM45	-
COM11	Row36	Ram36	Row44	Ram44	Row36	Ram44	Row36	RAM44	-
COM12	Row35	Ram35	Row43	Ram43	Row35	Ram43	Row35	RAM43	-
COM13	Row34	Ram34	Row42	Ram42	Row34	Ram42	Row34	RAM42	-
COM14	Row33	Ram33	Row41	Ram41	Row33	Ram41	Row33	RAM41	-
COM15	Row32	Ram32	Row40	Ram40	Row32	Ram40	Row32	RAM40	-
COM16	Row31	Ram31	Row39	Ram39	Row31	Ram39	Row31	RAM39	-
COM17	Row30	Ram30	Row38	Ram38	Row30	Ram38	Row30	RAM38	-
COM18	Row29	Ram29	Row37	Ram37	Row29	Ram37	Row29	RAM37	-
COM19	Row28	Ram28	Row36	Ram36	Row28	Ram36	Row28	RAM36	-
COM20	Row27	Ram27	Row35	Ram35	Row27	Ram35	Row27	RAM35	-
COM21	Row26	Ram26	Row34	Ram34	Row26	Ram34	Row26	RAM34	-
COM22	Row25	Ram25	Row33	Ram33	Row25	Ram33	Row25	RAM33	-
COM23	Row24	Ram24	Row32	Ram32	Row24	Ram32	Row24	RAM32	-
COM24	Row23	Ram23	Row31	Ram31	Row23	Ram31	Row23	RAM31	Row31 RAM47
COM25	Row22	Ram22	Row30	Ram30	Row22	Ram30	Row22	RAM30	Row30 RAM46
COM26	Row21	Ram21	Row29	Ram29	Row21	Ram29	Row21	RAM29	Row29 RAM45
COM27	Row20	Ram20	Row28	Ram28	Row20	Ram28	Row20	RAM28	Row28 RAM44
COM28	Row19	Ram19	Row27	Ram27	Row19	Ram27	Row19	RAM27	Row27 RAM43
COM29	Row18	Ram18	Row26	Ram26	Row18	Ram26	Row18	RAM26	Row26 RAM42
COM30	Row17	Ram17	Row25	Ram25	Row17	Ram25	Row17	RAM25	Row25 RAM41
COM31	Row16	Ram16	Row24	Ram24	Row16	Ram24	Row16	RAM24	Row24 RAM40
COM32	Row15	Ram15	Row23	Ram23	Row15	Ram23	Row15	RAM23	Row23 RAM39
COM33	Row14	Ram14	Row22	Ram22	Row14	Ram22	Row14	RAM22	Row22 RAM38
COM34	Row13	Ram13	Row21	Ram21	Row13	Ram21	Row13	RAM21	Row21 RAM37
COM35	Row12	Ram12	Row20	Ram20	Row12	Ram20	Row12	RAM20	Row20 RAM36
COM36	Row11	Ram11	Row19	Ram19	Row11	Ram19	Row11	RAM19	Row19 RAM35
COM37	Row10	Ram10	Row18	Ram18	Row10	Ram18	Row10	RAM18	Row18 RAM34
COM38	Row9	Ram9	Row17	Ram17	Row9	Ram17	Row9	RAM17	Row17 RAM33
COM39	Row8	Ram8	Row16	Ram16	Row8	Ram16	Row8	RAM16	Row16 RAM32
COM40	Row7	Ram7	Row15	Ram15	Row7	Ram15	Row7	RAM15	Row15 RAM31
COM41	Row6	Ram6	Row14	Ram14	Row6	Ram14	Row6	RAM14	Row14 RAM30
COM42	Row5	Ram5	Row13	Ram13	Row5	Ram13	Row5	RAM13	Row13 RAM29
COM43	Row4	Ram4	Row12	Ram12	Row4	Ram12	Row4	RAM12	Row12 RAM28
COM44	Row3	Ram3	Row11	Ram11	Row3	Ram11	Row3	RAM11	Row11 RAM27
COM45	Row2	Ram2	Row10	Ram10	Row2	Ram10	Row2	RAM10	Row10 RAM26
COM46	Row1	Ram1	Row9	Ram9	Row1	Ram9	Row9	RAM9	Row9 RAM25
COM47	Row0	Ram0	Row8	Ram8	Row0	Ram8	Row8	RAM8	Row8 RAM24

Hardware pin name	Output												Set MUX ratio(A8) COM Normal / Remapped (C0 / C8) Display offset (D3) Display start line (40 - 7F)	
	48		48		48		40		40		40			
	Normal		Normal		Normal		Normal		Normal		Normal			
	0	0	8	0	0	0	0	0	8	0	0	8		
COM0	Row0	RAM0	Row8	RAM8	Row0	RAM8	Row0	RAM0	Row8	RAM8	Row0	RAM8		
COM1	Row1	RAM1	Row9	RAM9	Row1	RAM9	Row1	RAM1	Row9	RAM9	Row1	RAM9		
COM2	Row2	RAM2	Row10	RAM10	Row2	RAM10	Row2	RAM2	Row10	RAM10	Row2	RAM10		
COM3	Row3	RAM3	Row11	RAM11	Row3	RAM11	Row3	RAM3	Row11	RAM11	Row3	RAM11		
COM4	Row4	RAM4	Row12	RAM12	Row4	RAM12	Row4	RAM4	Row12	RAM12	Row4	RAM12		
COM5	Row5	RAM5	Row13	RAM13	Row5	RAM13	Row5	RAM5	Row13	RAM13	Row5	RAM13		
COM6	Row6	RAM6	Row14	RAM14	Row6	RAM14	Row6	RAM6	Row14	RAM14	Row6	RAM14		
COM7	Row7	RAM7	Row15	RAM15	Row7	RAM15	Row7	RAM7	Row15	RAM15	Row7	RAM15		
COM8	Row8	RAM8	Row16	RAM16	Row8	RAM16	Row8	RAM8	Row16	RAM16	Row8	RAM16		
COM9	Row9	RAM9	Row17	RAM17	Row9	RAM17	Row9	RAM9	Row17	RAM17	Row9	RAM17		
COM10	Row10	RAM10	Row18	RAM18	Row10	RAM18	Row10	RAM10	Row18	RAM18	Row10	RAM18		
COM11	Row11	RAM11	Row19	RAM19	Row11	RAM19	Row11	RAM11	Row19	RAM19	Row11	RAM19		
COM12	Row12	RAM12	Row20	RAM20	Row12	RAM20	Row12	RAM12	Row20	RAM20	Row12	RAM20		
COM13	Row13	RAM13	Row21	RAM21	Row13	RAM21	Row13	RAM13	Row21	RAM21	Row13	RAM21		
COM14	Row14	RAM14	Row22	RAM22	Row14	RAM22	Row14	RAM14	Row22	RAM22	Row14	RAM22		
COM15	Row15	RAM15	Row23	RAM23	Row15	RAM23	Row15	RAM15	Row23	RAM23	Row15	RAM23		
COM16	Row16	RAM16	Row24	RAM24	Row16	RAM24	Row16	RAM16	Row24	RAM24	Row16	RAM24		
COM17	Row17	RAM17	Row25	RAM25	Row17	RAM25	Row17	RAM17	Row25	RAM25	Row17	RAM25		
COM18	Row18	RAM18	Row26	RAM26	Row18	RAM26	Row18	RAM18	Row26	RAM26	Row18	RAM26		
COM19	Row19	RAM19	Row27	RAM27	Row19	RAM27	Row19	RAM19	Row27	RAM27	Row19	RAM27		
COM20	Row20	RAM20	Row28	RAM28	Row20	RAM28	Row20	RAM20	Row28	RAM28	Row20	RAM28		
COM21	Row21	RAM21	Row29	RAM29	Row21	RAM29	Row21	RAM21	Row29	RAM29	Row21	RAM29		
COM22	Row22	RAM22	Row30	RAM30	Row22	RAM30	Row22	RAM22	Row30	RAM30	Row22	RAM30		
COM23	Row23	RAM23	Row31	RAM31	Row23	RAM31	Row23	RAM23	Row31	RAM31	Row23	RAM31		
COM24	Row24	RAM24	Row32	RAM32	Row24	RAM32	Row24	RAM24	Row32	RAM32	Row24	RAM32		
COM25	Row25	RAM25	Row33	RAM33	Row25	RAM33	Row25	RAM25	Row33	RAM33	Row25	RAM33		
COM26	Row26	RAM26	Row34	RAM34	Row26	RAM34	Row26	RAM26	Row34	RAM34	Row26	RAM34		
COM27	Row27	RAM27	Row35	RAM35	Row27	RAM35	Row27	RAM27	Row35	RAM35	Row27	RAM35		
COM28	Row28	RAM28	Row36	RAM36	Row28	RAM36	Row28	RAM28	Row36	RAM36	Row28	RAM36		
COM29	Row29	RAM29	Row37	RAM37	Row29	RAM37	Row29	RAM29	Row37	RAM37	Row29	RAM37		
COM30	Row30	RAM30	Row38	RAM38	Row30	RAM38	Row30	RAM30	Row38	RAM38	Row30	RAM38		
COM31	Row31	RAM31	Row39	RAM39	Row31	RAM39	Row31	RAM31	Row39	RAM39	Row31	RAM39		
COM32	Row32	RAM32	Row40	RAM40	Row32	RAM40	Row32	RAM32	-	-	Row32	RAM40		
COM33	Row33	RAM33	Row41	RAM41	Row33	RAM41	Row33	RAM33	-	-	Row33	RAM41		
COM34	Row34	RAM34	Row42	RAM42	Row34	RAM42	Row34	RAM34	-	-	Row34	RAM42		
COM35	Row35	RAM35	Row43	RAM43	Row35	RAM43	Row35	RAM35	-	-	Row35	RAM43		
COM36	Row36	RAM36	Row44	RAM44	Row36	RAM44	Row36	RAM36	-	-	Row36	RAM44		
COM37	Row37	RAM37	Row45	RAM45	Row37	RAM45	Row37	RAM37	-	-	Row37	RAM45		
COM38	Row38	RAM38	Row46	RAM46	Row38	RAM46	Row38	RAM38	-	-	Row38	RAM46		
COM39	Row39	RAM39	Row47	RAM47	Row39	RAM47	Row39	RAM39	-	-	Row39	RAM47		
COM40	Row40	RAM40	Row40	RAM40	Row40	RAM48	-	-	Row0	RAM0	-	-		
COM41	Row41	RAM41	Row41	RAM41	Row41	RAM49	-	-	Row1	RAM1	-	-		
COM42	Row42	RAM42	Row42	RAM42	Row42	RAM50	-	-	Row2	RAM2	-	-		
COM43	Row43	RAM43	Row43	RAM43	Row43	RAM51	-	-	Row3	RAM3	-	-		
COM44	Row44	RAM44	Row44	RAM44	Row44	RAM52	-	-	Row4	RAM4	-	-		
COM45	Row45	RAM45	Row45	RAM45	Row45	RAM53	-	-	Row5	RAM5	-	-		
COM46	Row46	RAM46	Row46	RAM46	Row46	RAM54	-	-	Row6	RAM6	-	-		
COM47	Row47	RAM47	Row47	RAM47	Row47	RAM55	-	-	Row7	RAM7	-	-		

Set Display Clock Divide Ratio/ Oscillator Frequency

This command is used to set the frequency of the internal display clocks, DCLKs. It is defined as the divide ratio (Value from 1 to 16) used to divide the oscillator frequency. POR is 0000b which means the divide ratio is 1. Frame frequency is determined by divide ratio, number of display clocks per row, MUX ratio and oscillator frequency.

Set Area Colour Mode on/off

This command is used to enable area colour mode. POR is mono mode.

Set Low Power Display Mode

This is a double byte command. This command is set to reduce power consumption during IC operation.

Set Pre-charge period

This command is used to set the duration of the pre-charge period. The interval is counted in number of DCLK. POR is 2 DCLK.

Set COM pins hardware configuration

This command is to set the COM signals pin configuration (sequential or alternative) to match the OLED panel hardware layout

Alternative COM pin configuration (POR):

COM46, 44, 42...0	SEG0, 1, 2... 103	COM1, 3, 5...47
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Sequential COM pin configuration:

COM23, 22, 21...0	SEG0, 1, 2... 103	COM24, 25, 26...47
--------------------------	--------------------------	---------------------------

NOP

No Operation Command

Status register Read

This command is issued by setting D/C# Low during a data read (refer to Figure 8 and Figure 9 parallel interface waveform). It allows the MCU to monitor the internal status of the chip. No status read is provided for serial mode.

Set DC-DC on/off

This command is to control the DC-DC voltage converter. The converter will be turned on by issuing this command then DISPLAY ON command. The panel display must be off while issuing this command. POR the DC-DC will be turned on.

Set V_{COMH} Voltage

This command sets the high voltage level of common pins, V_{COMH} , when it is selected to generate internally by command ADh. The level of V_{COMH} is programmed with reference to V_{REF} .

11 MAXIMUM RATINGS

Table 7 - Maximum Ratings (Voltage Reference to V_{ss})

Symbol	Parameter	Value	Unit
V _{DD}	Supply Voltage	-0.3 to +4.0	V
V _{CC}		0.0 to 18.0	V
V _{REF}		0.0 to 18.0	V
V _{COMH}	Supply Voltage/Output voltage	0.0 to 18.0	V
-	SEG/COM output voltage	0.0 to 18.0	V
V _{in}	Input voltage	V _{ss} -0.3 to V _{dd} +0.3	V
T _A	Operating Temperature	-40 to +85	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C

Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description.

12 DC CHARACTERISTICS

Table 8 - DC Characteristics

(Unless otherwise specified, Voltage Referenced to V_{SS}, V_{DD} = 2.4 to 3.5V, T_A = 25°C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V _{CC}	Operating Voltage	-	7	12	16	V
V _{DD}	Logic Supply Voltage	-	2.4	-	3.5	V
V _{DD}	Logic Supply Voltage (internal DC/DC enable)	-	3.0	-	3.5	V
V _{OH}	High Logic Output Level	I _{OUT} = 100uA, 3.3MHz	0.9*V _{DD}	-	V _{DD}	V
V _{OL}	Low Logic Output Level	I _{OUT} = 100uA, 3.3MHz	0	-	0.1*V _{DD}	V
V _{IH}	High Logic Input Level	I _{OUT} = 100uA, 3.3MHz	0.8*V _{DD}	-	V _{DD}	V
V _{IL}	Low Logic Input Level	I _{OUT} = 100uA, 3.3MHz	0	-	0.2*V _{DD}	V
I _{CC, SLEEP}	Sleep mode Current	V _{DD} =2.7V, display OFF, No panel attached	-15	-	+15	uA
I _{DD, SLEEP}	Sleep mode Current	V _{DD} =2.7V, display OFF, No panel attached	-15	-	+15	uA
I _{CC}	V _{CC} Supply Current	Contrast = FF	-	550	-	uA
I _{DD}	V _{DD} Supply Current	Contrast = FF	-	190	-	uA
I _{SEG}	Segment Output Current	Contrast=FF	285	320	355	uA
	V _{DD} =2.7V, V _{CC} =12V, I _{REF} =10uA, Display on, Segment pin under test is connected with a 20K resistive load to V _{SS}	Contrast=AF	-	220	-	
		Contrast=5F	-	120	-	
		Contrast=0F	-	20	-	
Dev	Segment output current uniformity	Dev = (I _{SEG} - I _{MID}) / I _{MID} I _{MID} = (I _{MAX} + I _{MIN}) / 2 I _{SEG[0:103]} = Segment current at contrast = FF	-	-	±3	%
Adj. Dev	Adjacent pin output current uniformity (contrast = FF)	Adj Dev = (I[n] - I[n+1]) / (I[n] + I[n+1])	-	±2.0	--	%
Vcc	DC-DC converter output voltage	V _{DD} input=3V, L=10uH; R1=450Kohm; R2=50Kohm; I _{CC} = 20mA(loader)	11.0	12.0	13.0	V
		-	7	-	16	
Pwr	DC-DC Converter output power	V _{DD} input=3V, L=10uH; V _{CC} = 12V	-	-	400	mW

13 AC CHARACTERISTICS

Table 9 - AC Characteristics

(Unless otherwise specified, Voltage Referenced to V_{SS} , $V_{DD} = 2.4$ to $3.5V$, $T_A = 25^\circ C$.)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
F_{osc}	Oscillation Frequency of Display Timing Generator	$V_{DD} = 2.7V$	260	280	310	kHz
F_{frm}	Frame Frequency for 48 MUX Mode	104x48 Graphic Display Mode, Display ON, Internal Oscillator Enabled	-	$F_{osc} \times 1/(D \times K^* 48)$	-	Hz

D: divide ratio (default value = 1)

K: number of display clocks (default value = 54)

Refer to command table for detail description

14 Timing characteristics

Table 10 - I²C Interface Timing Characteristics (V_{DD}-V_{SS}=2.4 to 3.5V, T_A=-40 to 85° C)

Symbol	Parameter	Min	Typ	Max	Unit
t _{cycle}	Clock Cycle Time	2.5	-	-	us
t _{HSTART}	Start condition Hold Time	0.6	-	-	us
t _{HD}	Data Hold Time	300	-	-	ns
t _{SD}	Data Setup Time	100	-	-	ns
t _{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t _{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t _R	Rise Time for data and clock pin	-	-	300	ns
t _F	Fall Time for data and clock pin	-	-	300	ns
t _{IDLE}	Idle Time before a new transmission can start	1.3	-	-	us

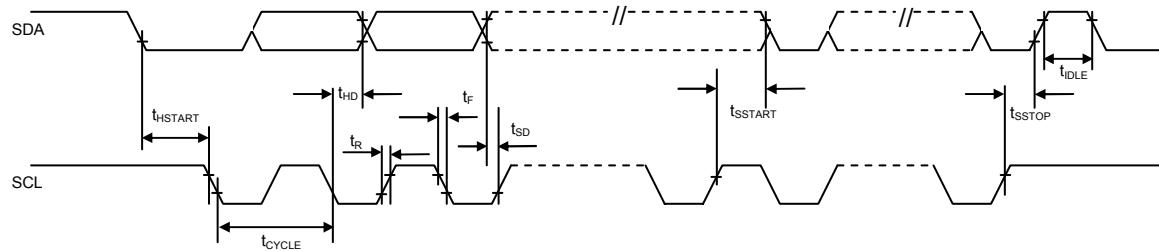


Figure 17 - I²C interface characteristics

Table 11 - 6800-Series MPU Parallel Interface Timing Characteristics

($V_{DD} - V_{SS} = 2.4$ to $3.5V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

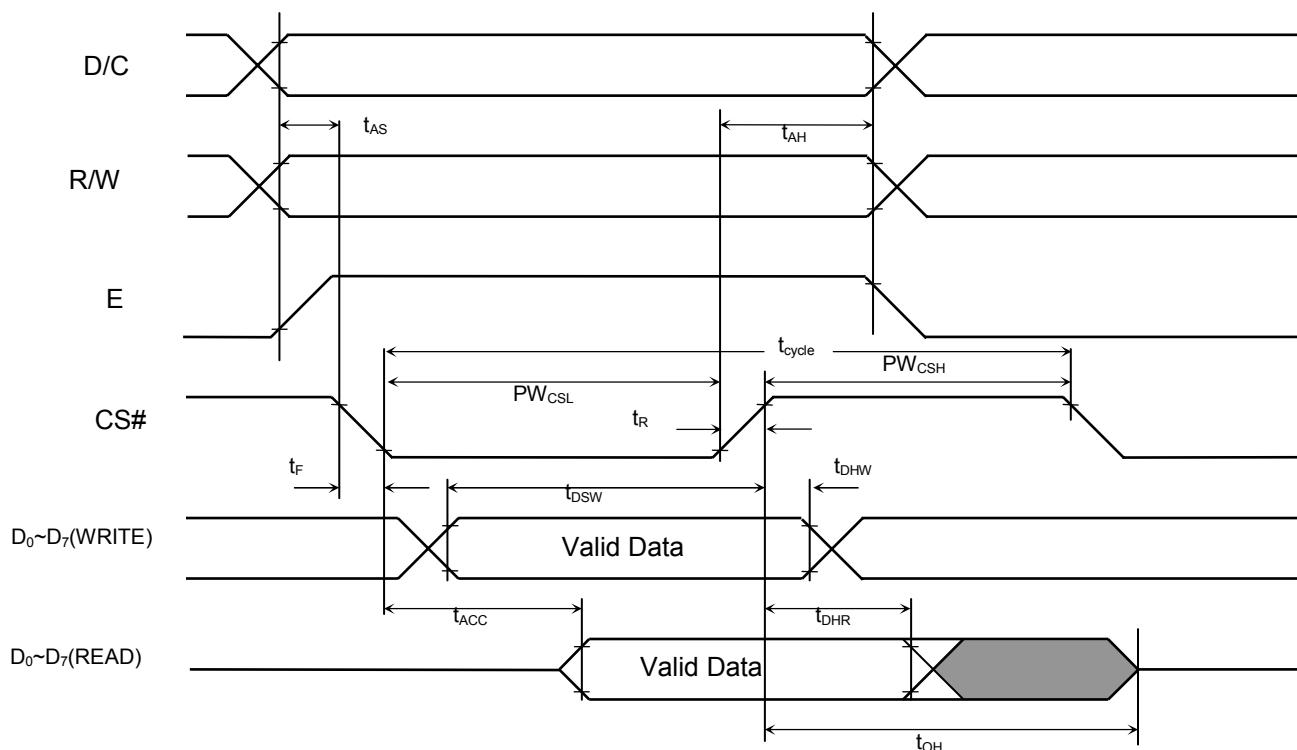


Figure 18 - 6800-series MPU parallel interface characteristics

Table 12 - 8080-Series MPU Parallel Interface Timing Characteristics

($V_{DD} - V_{SS} = 2.4$ to $3.5V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

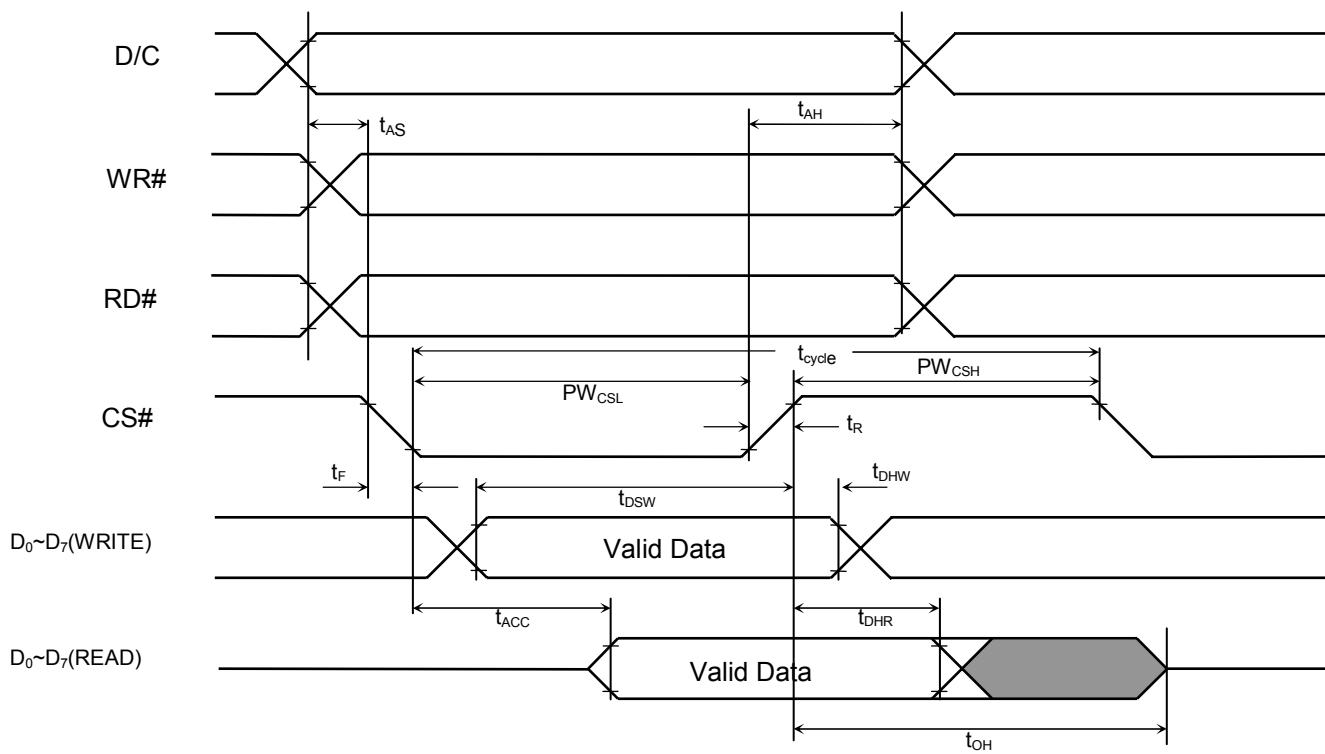


Figure 19 - 8080-series MPU parallel interface characteristics

Table 13 - Serial Interface Timing Characteristics

($V_{DD} - V_{SS} = 2.4$ to $3.5V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	250	-	-	ns
t_{AS}	Address Setup Time	150	-	-	ns
t_{AH}	Address Hold Time	150	-	-	ns
t_{CSS}	Chip Select Setup Time	120	-	-	ns
t_{CSH}	Chip Select Hold Time	60	-	-	ns
t_{DSW}	Write Data Setup Time	100	-	-	ns
t_{DHW}	Write Data Hold Time	100	-	-	ns
t_{CLKL}	Clock Low Time	100	-	-	ns
t_{CLKH}	Clock High Time	100	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

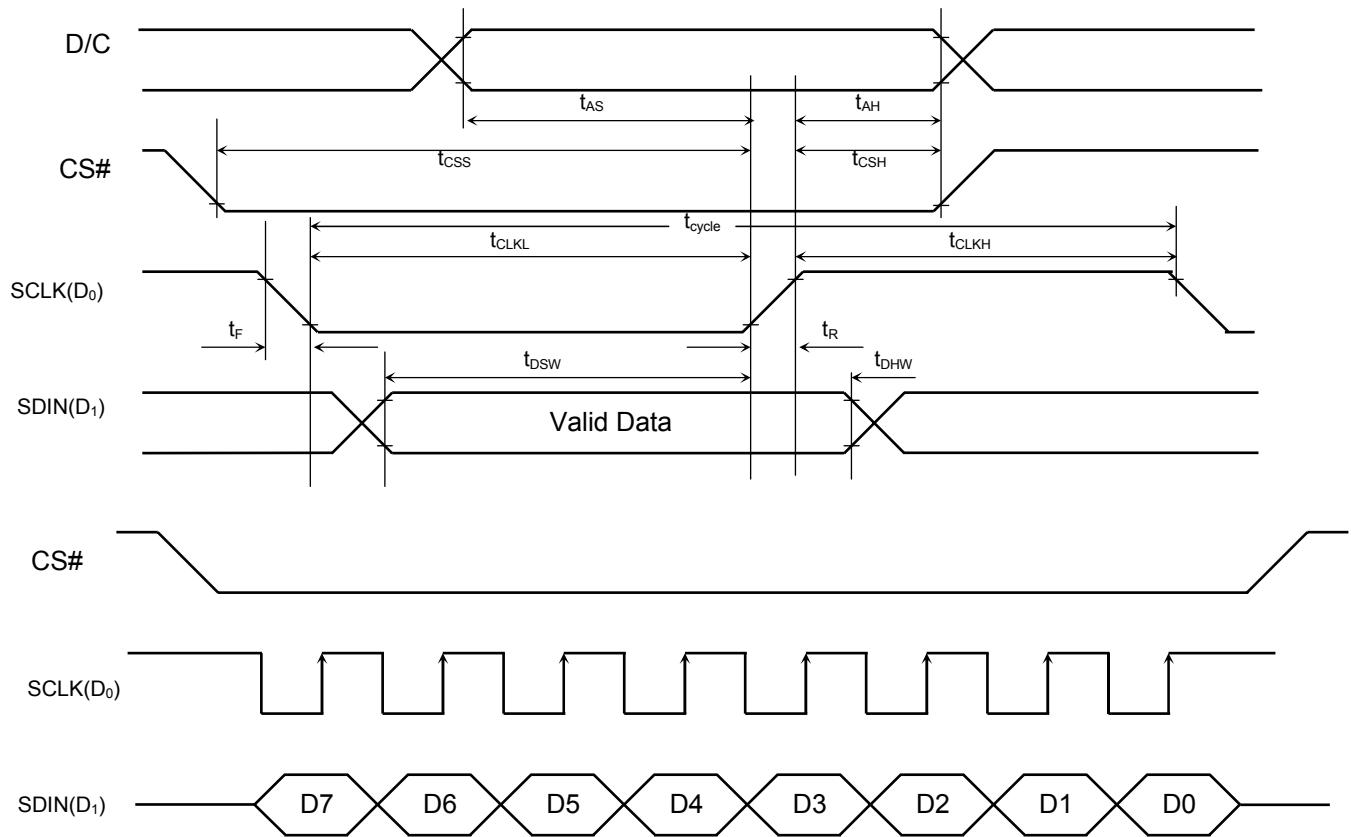
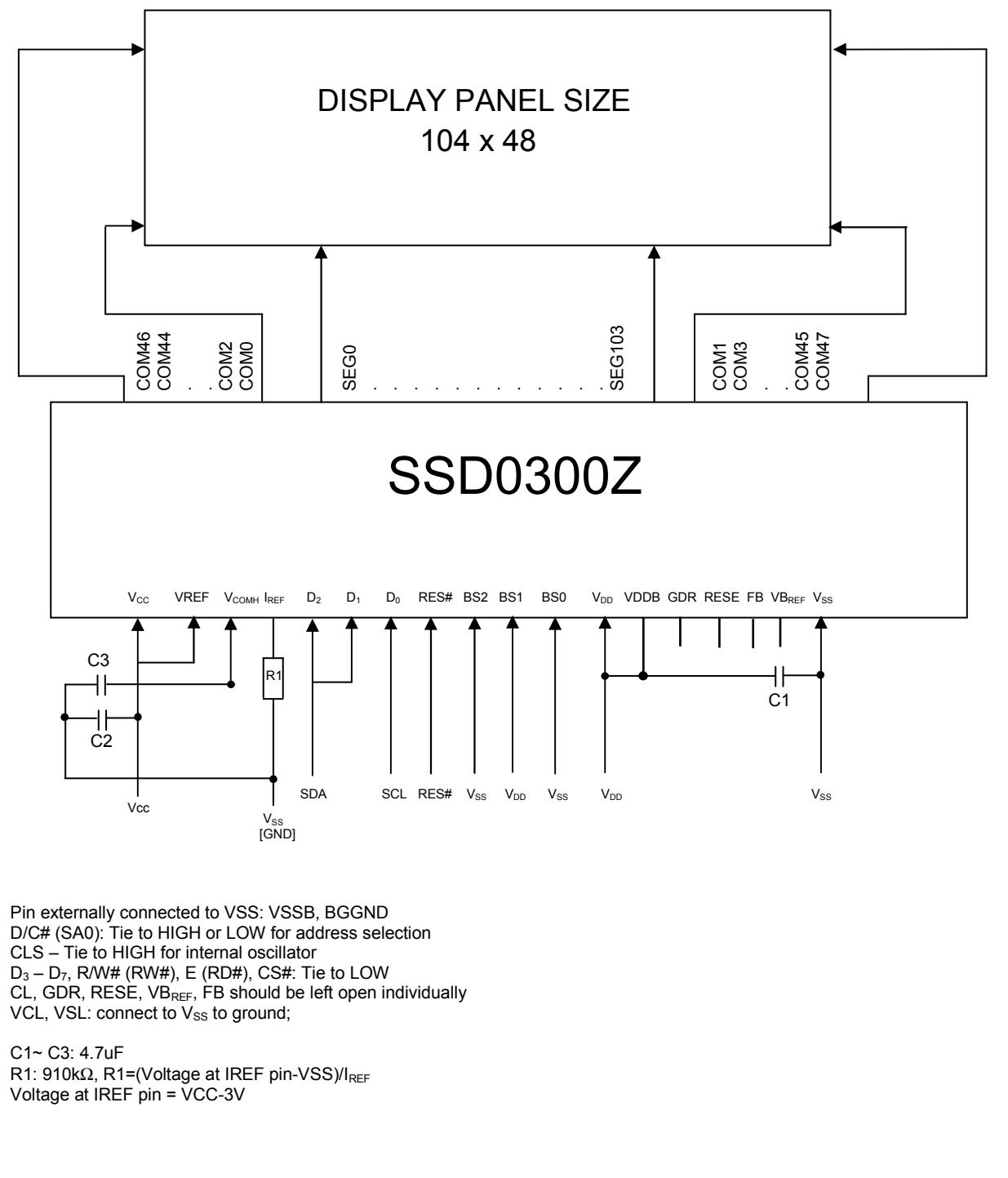


Figure 20 - Serial interface characteristics

15 APPLICATION EXAMPLE

Figure 21 - Application example for SSD0300

The typical configuration for I²C interface mode & externally V_{CC} are shown in the following diagram:
(V_{DD}=2.7V, V_{CC}=V_{REF}=12V, I_{REF}=10uA)



16 SSD0300TR1 TAB Package

SSD0300TR1 pin assignment

Figure 22 - SSD0300TR1 pin assignment

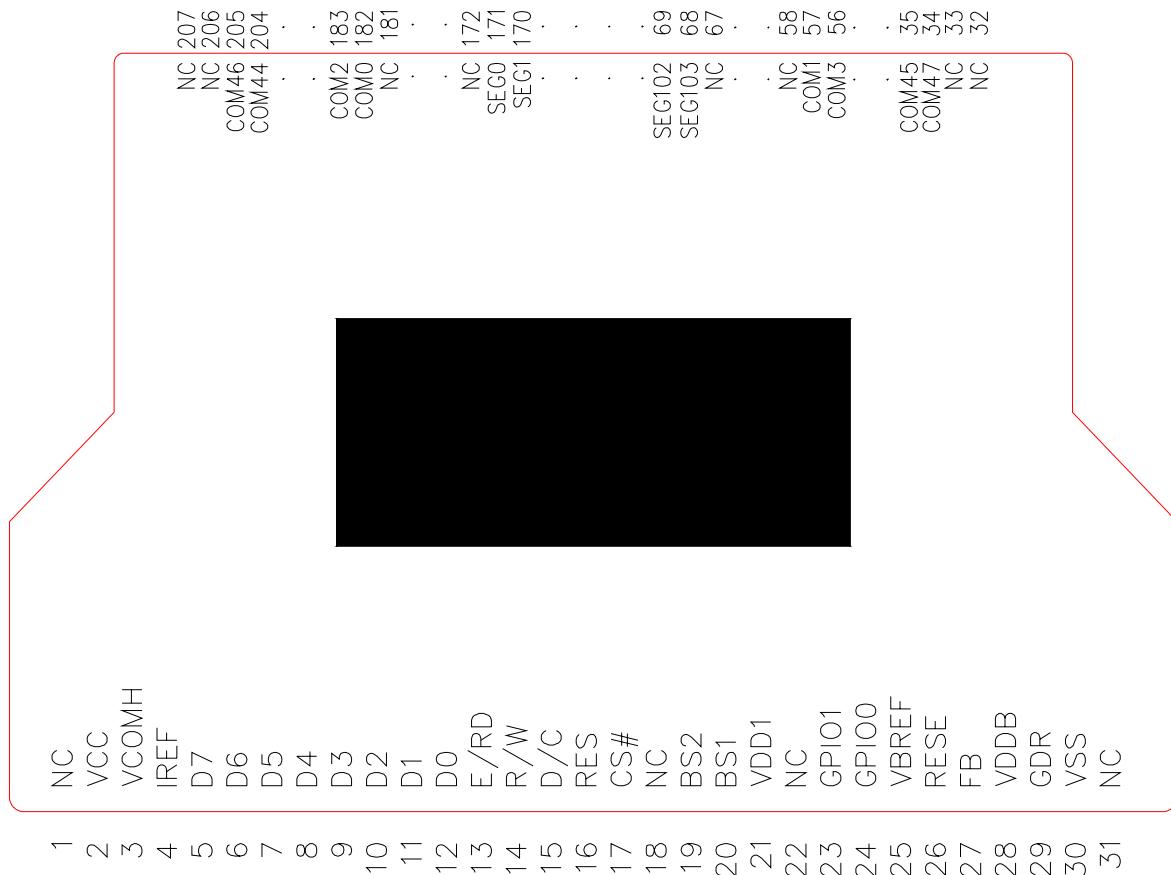
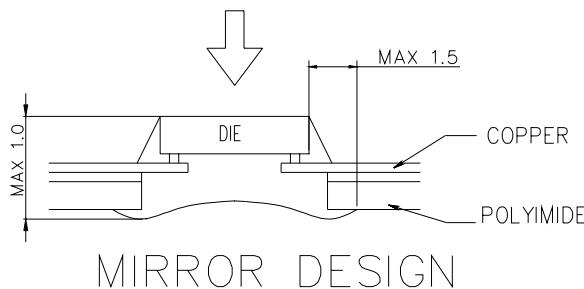
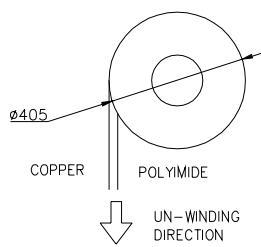
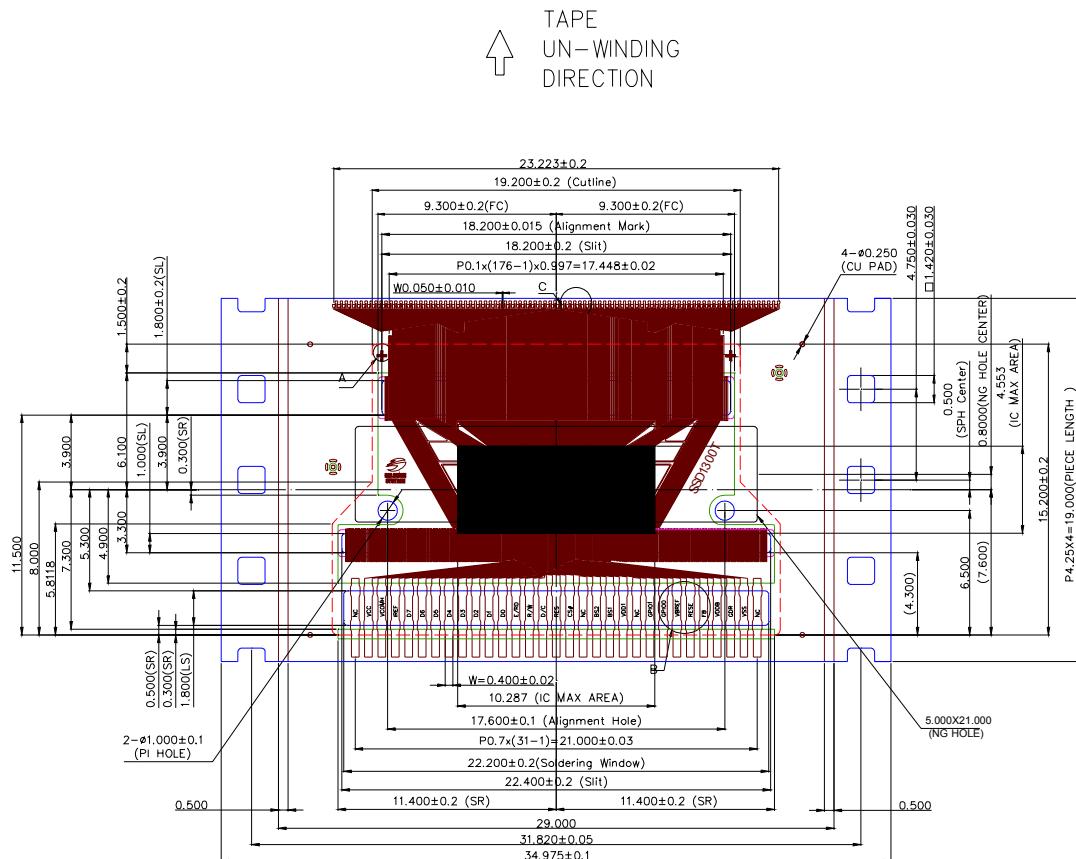


Table 14 - SSD0300TR1 pin assignment

Pin no.	Pin Name	Pin no.	Pin Name	Pin no.	Pin Name
1	NC	81	SEG90	161	SEG10
2	VCC	82	SEG89	162	SEG9
3	VCOMH	83	SEG88	163	SEG8
4	IREF	84	SEG87	164	SEG7
5	D7	85	SEG86	165	SEG6
6	D6	86	SEG85	166	SEG5
7	D5	87	SEG84	167	SEG4
8	D4	88	SEG83	168	SEG3
9	D3	89	SEG82	169	SEG2
10	D2	90	SEG81	170	SEG1
11	D1	91	SEG80	171	SEG0
12	D0	92	SEG79	172	NC
13	E	93	SEG78	173	NC
14	R/W	94	SEG77	174	NC
15	D/C	95	SEG76	175	NC
16	RES#	96	SEG75	176	NC
17	CS#	97	SEG74	177	NC
18	NC	98	SEG73	178	NC
19	BS2	99	SEG72	179	NC
20	BS1	100	SEG71	180	NC
21	VDD1	101	SEG70	181	NC
22	NC	102	SEG69	182	COM0
23	GPIO1	103	SEG68	183	COM2
24	GPIO0	104	SEG67	184	COM4
25	VBREF	105	SEG66	185	COM6
26	RESE	106	SEG65	186	COM8
27	FB	107	SEG64	187	COM10
28	VDDB	108	SEG63	188	COM12
29	GDR	109	SEG62	189	COM14
30	VSS	110	SEG61	190	COM16
31	NC	111	SEG60	191	COM18
32	NC	112	SEG59	192	COM20
33	NC	113	SEG58	193	COM22
34	COM47	114	SEG57	194	COM24
35	COM45	115	SEG56	195	COM26
36	COM43	116	SEG55	196	COM28
37	COM41	117	SEG54	197	COM30
38	COM39	118	SEG53	198	COM32
39	COM37	119	SEG52	199	COM34
40	COM35	120	SEG51	200	COM36
41	COM33	121	SEG50	201	COM38
42	COM31	122	SEG49	202	COM40
43	COM29	123	SEG48	203	COM42
44	COM27	124	SEG47	204	COM44
45	COM25	125	SEG46	205	COM46
46	COM23	126	SEG45	206	NC
47	COM21	127	SEG44	207	NC
48	COM19	128	SEG43		
49	COM17	129	SEG42		
50	COM15	130	SEG41		
51	COM13	131	SEG40		
52	COM11	132	SEG39		
53	COM9	133	SEG38		
54	COM7	134	SEG37		
55	COM5	135	SEG36		
56	COM3	136	SEG35		
57	COM1	137	SEG34		
58	NC	138	SEG33		
59	NC	139	SEG32		
60	NC	140	SEG31		
61	NC	141	SEG30		
62	NC	142	SEG29		
63	NC	143	SEG28		
64	NC	144	SEG27		
65	NC	145	SEG26		
66	NC	146	SEG25		
67	NC	147	SEG24		
68	SEG103	148	SEG23		
69	SEG102	149	SEG22		
70	SEG101	150	SEG21		
71	SEG100	151	SEG20		
72	SEG99	152	SEG19		
73	SEG98	153	SEG18		
74	SEG97	154	SEG17		
75	SEG96	155	SEG16		
76	SEG95	156	SEG15		
77	SEG94	157	SEG14		
78	SEG93	158	SEG13		
79	SEG92	159	SEG12		
80	SEG91	160	SEG11		

SSD0300TR1 TAB details dimensions

Figure 23- SSD0300TR1 detail dimensions



Specification:

1. GENERAL TOLERANCE: ± 0.05 mm

2. MATERIAL

PI: $75 \pm 8 \mu\text{m}$

CU: 18 ± 5 μm

ADHESIVE: 12

SR: 26 ± 14 um

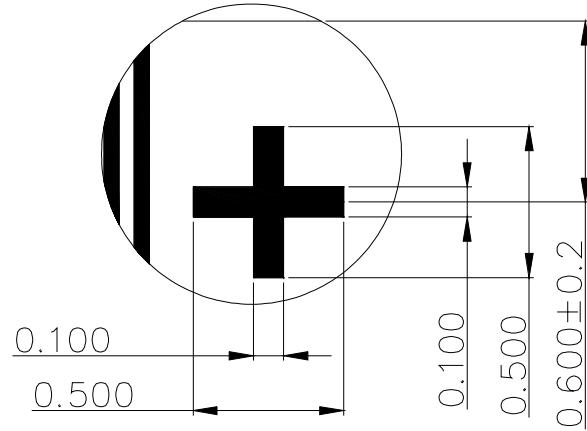
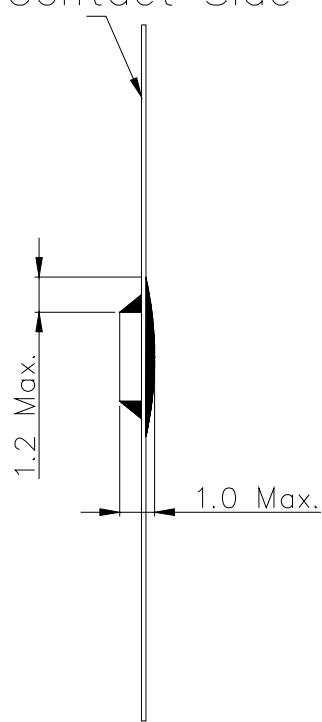
TOLERANCE ± 0.200 mm

FLEX COATING: Min 10 µm

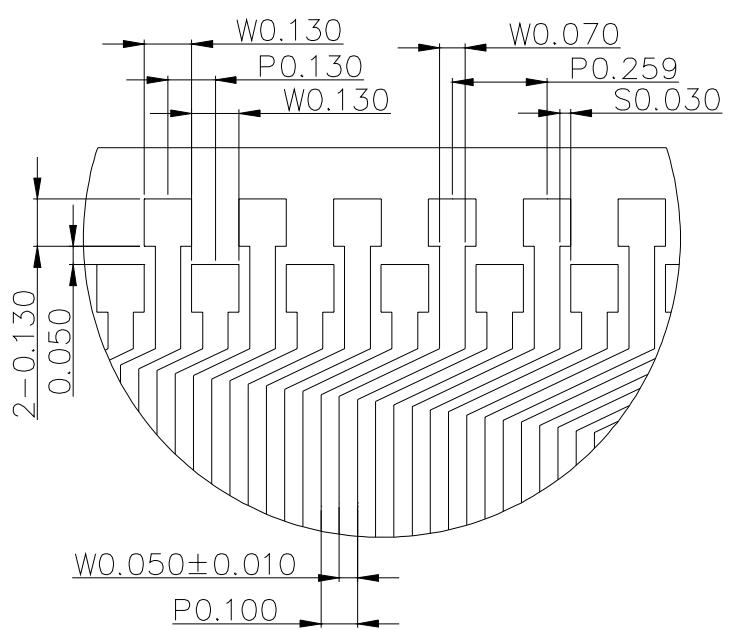
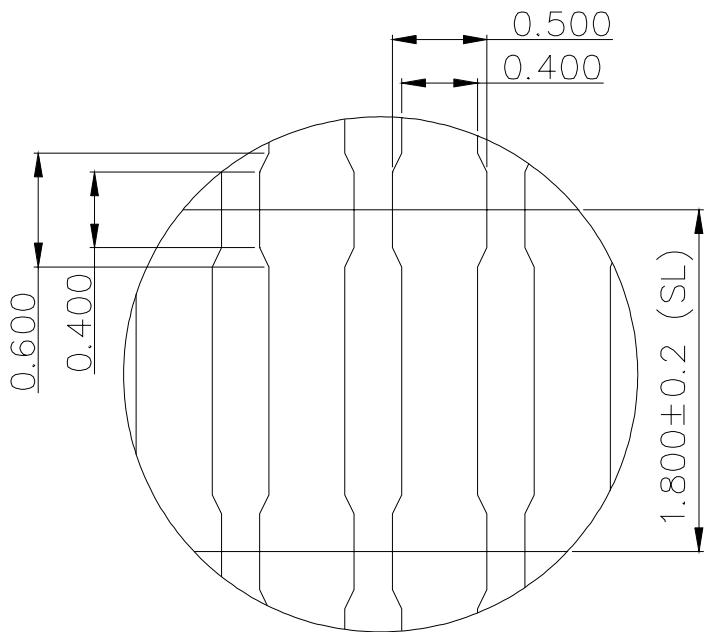
3. Plating : Sn 0.20 ± 0.05 um

4. TAPESITE: 4 SPH, 19 mm

Contact Side



Detail A Scale5:1
Tolerance: 0.02mm



Detail B Scale4:1

Detail C Scale5:1

17 SSD0300T3R1 TAB PACKAGE

SSD0300T3R1 pin assignment

Figure 24 - SSD0300T3R1 pin assignment (Copper view)

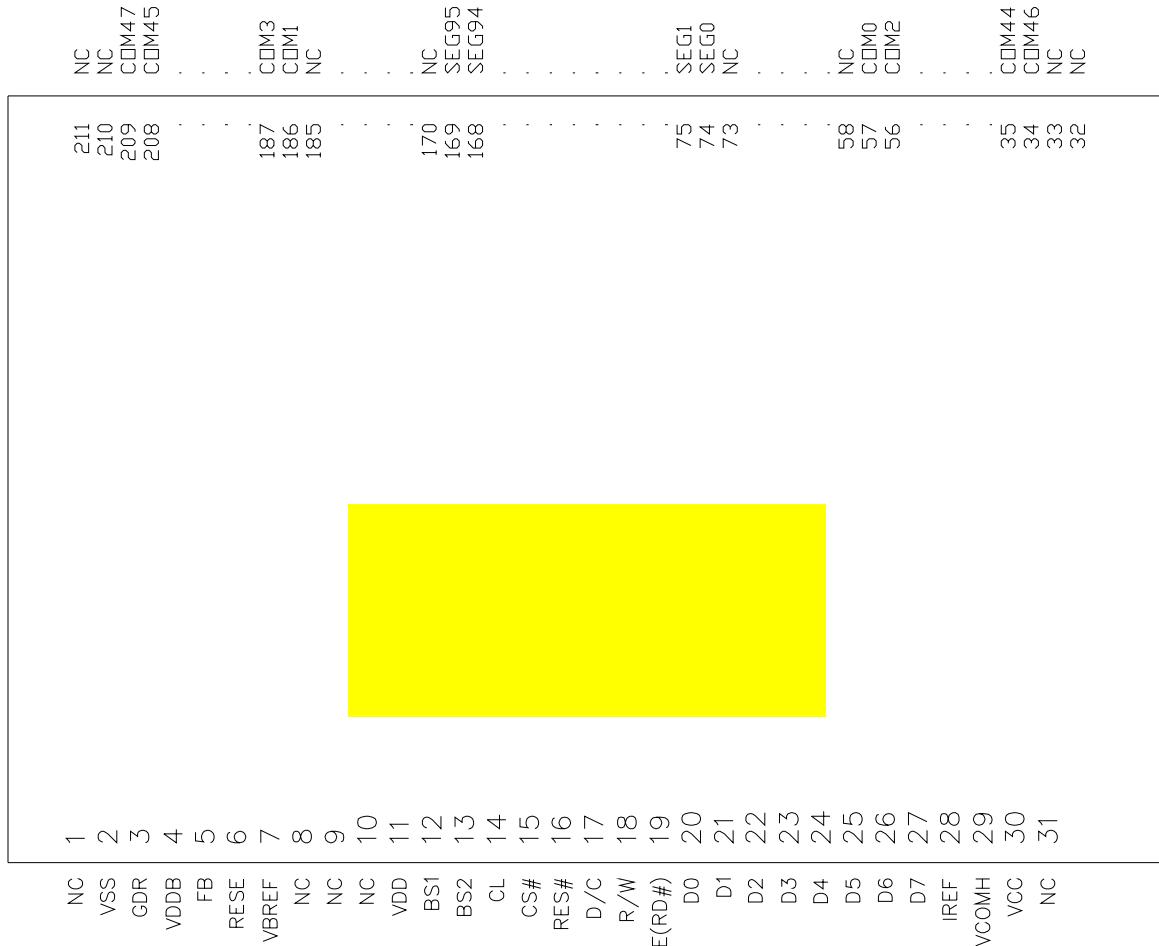
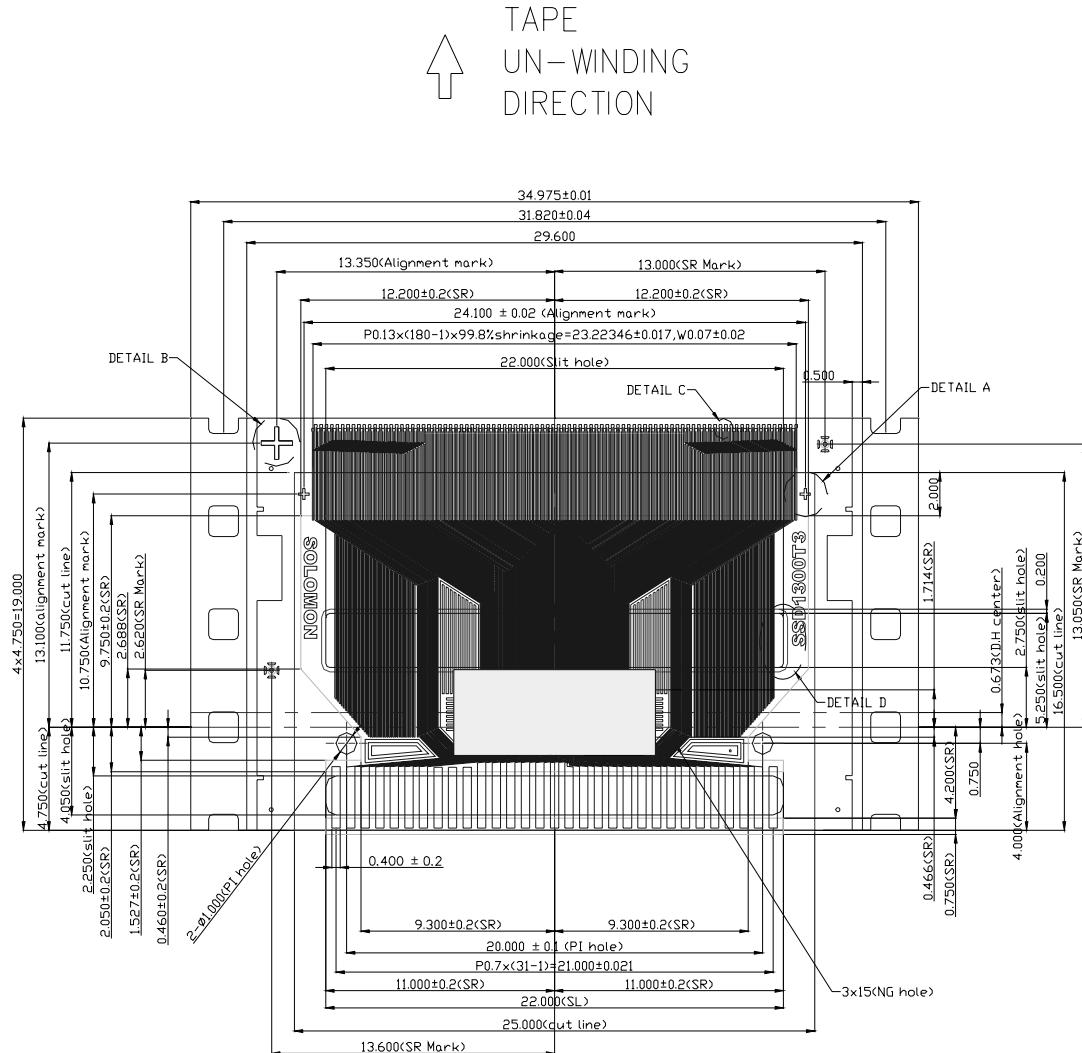


Table 15 - SSD0300T3R1 pin assignment

Pin no.	Pin name						
1	NC	61	NC	121	SEG47	181	NC
2	VSS	62	NC	122	SEG48	182	NC
3	GDR	63	NC	123	SEG49	183	NC
4	VDDB	64	NC	124	SEG50	184	NC
5	FB	65	NC	125	SEG51	185	NC
6	RESE	66	NC	126	SEG52	186	COM1
7	VBREF	67	NC	127	SEG53	187	COM3
8	NC	68	NC	128	SEG54	188	COM5
9	NC	69	NC	129	SEG55	189	COM7
10	NC	70	NC	130	SEG56	190	COM9
11	VDD1	71	NC	131	SEG57	191	COM11
12	BS1	72	NC	132	SEG58	192	COM13
13	BS2	73	NC	133	SEG59	193	COM15
14	CL	74	SEG0	134	SEG60	194	COM17
15	CS#	75	SEG1	135	SEG61	195	COM19
16	RESE	76	SEG2	136	SEG62	196	COM21
17	D/C	77	SEG3	137	SEG63	197	COM23
18	R/W	78	SEG4	138	SEG64	198	COM25
19	E/RD	79	SEG5	139	SEG65	199	COM27
20	D0	80	SEG6	140	SEG66	200	COM29
21	D1	81	SEG7	141	SEG67	201	COM31
22	D2	82	SEG8	142	SEG68	202	COM33
23	D3	83	SEG9	143	SEG69	203	COM35
24	D4	84	SEG10	144	SEG70	204	COM37
25	D5	85	SEG11	145	SEG71	205	COM39
26	D6	86	SEG12	146	SEG72	206	COM41
27	D7	87	SEG13	147	SEG73	207	COM43
28	IREF	88	SEG14	148	SEG74	208	COM45
29	VCOMH	89	SEG15	149	SEG75	209	COM47
30	VCC	90	SEG16	150	SEG76	210	NC
31	NC	91	SEG17	151	SEG77	211	NC
32	NC	92	SEG18	152	SEG78		
33	NC	93	SEG19	153	SEG79		
34	COM46	94	SEG20	154	SEG80		
35	COM44	95	SEG21	155	SEG81		
36	COM42	96	SEG22	156	SEG82		
37	COM40	97	SEG23	157	SEG83		
38	COM38	98	SEG24	158	SEG84		
39	COM36	99	SEG25	159	SEG85		
40	COM34	100	SEG26	160	SEG86		
41	COM32	101	SEG27	161	SEG87		
42	COM30	102	SEG28	162	SEG88		
43	COM28	103	SEG29	163	SEG89		
44	COM26	104	SEG30	164	SEG90		
45	COM24	105	SEG31	165	SEG91		
46	COM22	106	SEG32	166	SEG92		
47	COM20	107	SEG33	167	SEG93		
48	COM18	108	SEG34	168	SEG94		
49	COM16	109	SEG35	169	SEG95		
50	COM14	110	SEG36	170	NC		
51	COM12	111	SEG37	171	NC		
52	COM10	112	SEG38	172	NC		
53	COM8	113	SEG39	173	NC		
54	COM6	114	SEG40	174	NC		
55	COM4	115	SEG41	175	NC		
56	COM2	116	SEG42	176	NC		
57	COM0	117	SEG43	177	NC		
58	NC	118	SEG44	178	NC		
59	NC	119	SEG45	179	NC		
60	NC	120	SEG46	180	NC		

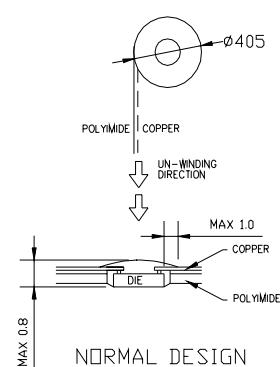
SSD0300T3R1 TAB details dimensions

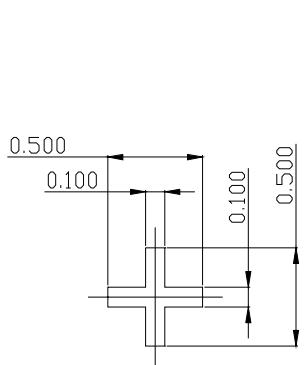
Figure 25- SSD0300T3R1 detail dimensions



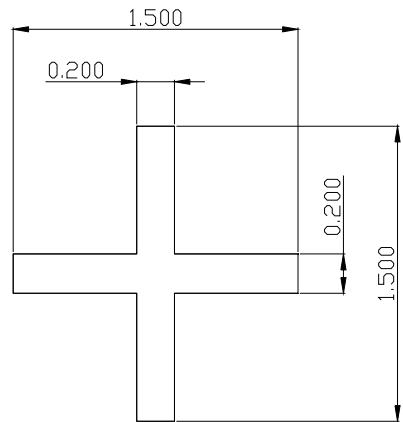
NOTE:

1. GENERAL TOLERANCE: $\pm 0.05\text{MM}$
2. MATERIAL
 - PI: UPLEX-S $75 \pm 6\mu\text{m}$
 - ADHESIVE: $12 \pm 2\mu\text{m}$
 - CU: $18\mu\text{m}$
 - SR: $26 \pm 14\mu\text{m}$
 - TOLERANCE ± 0.200
 - FLEX COATING: Min $10\mu\text{m}$
3. SN PLATING: $0.200 \pm 0.05\mu\text{m}$
4. TAPE SITE: 4 SPH, 19mm

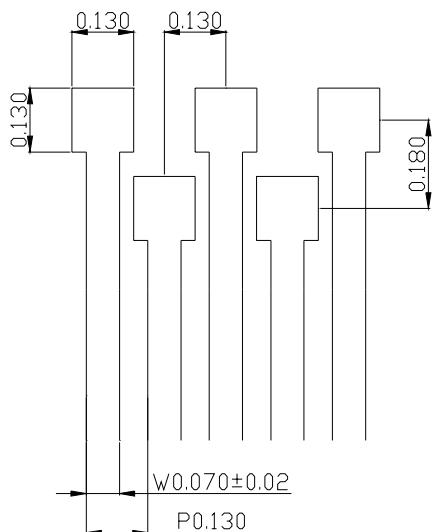




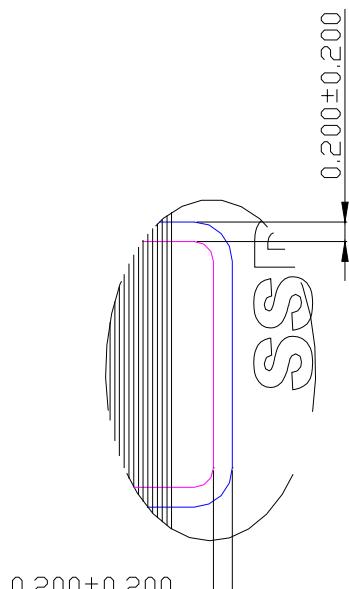
DETAIL A



DETAIL B



DETAIL C



DETAIL D

TAB marking Description

TAB marking is in form of "2X₆ X₅ X₄ X₃ X₂ X₁", where "2" stands for I²C TAB and "X"s are the other (normal) marks.

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